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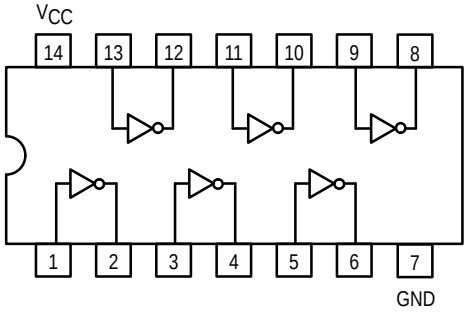
MOTOROLA

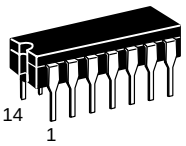
HEX INVERTER

SN54/74LS04

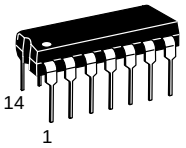


HEX INVERTER

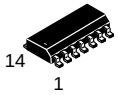
LOW POWER SCHOTTKY



J SUFFIX
CERAMIC
CASE 632-08



N SUFFIX
PLASTIC
CASE 646-06



D SUFFIX
SOIC
CASE 751A-02

ORDERING INFORMATION

SN54LSXXJ	Ceramic
SN74LSXXN	Plastic
SN74LSXXD	SOIC

GUARANTEED OPERATING RANGES

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	54 74	4.5 4.75	5.0 5.0	5.5 5.25	V
T_A	Operating Ambient Temperature Range	54 74	–55 0	25 25	125 70	°C
I_{OH}	Output Current — High	54, 74			–0.4	mA
I_{OL}	Output Current — Low	54 74			4.0 8.0	mA

DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

Symbol	Parameter		Limits Min	Limits Typ	Limits Max	Unit	Test Conditions	
V_{IH}	Input HIGH Voltage		2.0			V	Guaranteed Input HIGH Voltage for All Inputs	
V_{IL}	Input LOW Voltage	54			0.7	V	Guaranteed Input LOW Voltage for All Inputs	
		74			0.8			
V_{IK}	Input Clamp Diode Voltage			−0.65	−1.5	V	V_{CC} = MIN, I_{IN} = −18 mA	
V_{OH}	Output HIGH Voltage	54	2.5	3.5		V	V_{CC} = MIN, I_{OH} = MAX, V_{IN} = V_{IH} or V_{IL} per Truth Table	
		74	2.7	3.5		V		
V_{OL}	Output LOW Voltage	54, 74		0.25	0.4	V	I_{OL} = 4.0 mA	V_{CC} = V_{CC} MIN, V_{IN} = V_{IL} or V_{IH} per Truth Table
		74		0.35	0.5	V	I_{OL} = 8.0 mA	
I_{IH}	Input HIGH Current				20	μA	V_{CC} = MAX, V_{IN} = 2.7 V	
					0.1	mA	V_{CC} = MAX, V_{IN} = 7.0 V	
I_{IL}	Input LOW Current				−0.4	mA	V_{CC} = MAX, V_{IN} = 0.4 V	
I_{OS}	Short Circuit Current (Note 1)		−20		−100	mA	V_{CC} = MAX	
I_{CC}	Power Supply Current Total, Output HIGH				2.4	mA	V_{CC} = MAX	
	Total, Output LOW				6.6			

Note 1: Not more than one output should be shorted at a time, nor for more than 1 second.

AC CHARACTERISTICS (T_A = 25°C)

Symbol	Parameter	Limits Min	Limits Typ	Limits Max	Unit	Test Conditions
t_{PLH}	Turn-Off Delay, Input to Output		9.0	15	ns	V_{CC} = 5.0 V C_L = 15 pF
t_{PHL}	Turn-On Delay, Input to Output		10	15	ns	

FAIRCHILD SEMICONDUCTOR™

August 1986
Revised March 2000

DM74LS138 • DM74LS139 Decoder/Demultiplexer

General Description

These Schottky-clamped circuits are designed to be used in high-performance memory-decoding or data-routing applications, requiring very short propagation delay times. In high-performance memory systems these decoders can be used to minimize the effects of system decoding. When used with high-speed memories, the delay times of these decoders are usually less than the typical access time of the memory. This means that the effective system delay introduced by the decoder is negligible.

The DM74LS138 decodes one-of-eight lines, based upon the conditions at the three binary select inputs and the three enable inputs. Two active-low and one active-high enable inputs reduce the need for external gates or inverters when expanding. A 24-line decoder can be implemented with no external inverters, and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications.

The DM74LS139 comprises two separate two-line-to-four-line decoders in a single package. The active-low enable input can be used as a data line in demultiplexing applications.

All of these decoders/demultiplexers feature fully buffered inputs, presenting only one normalized load to its driving circuit. All inputs are clamped with high-performance Schottky diodes to suppress line-ringing and simplify system design.

Features

- Designed specifically for high speed:
  - Memory decoders
  - Data transmission systems
- DM74LS138 3-to-8-line decoders incorporates 3 enable inputs to simplify cascading and/or data reception
- DM74LS139 contains two fully independent 2-to-4-line decoders/demultiplexers
- Schottky clamped for high performance
- Typical propagation delay (3 levels of logic)
  - DM74LS138 21 ns
  - DM74LS139 21 ns
- Typical power dissipation
  - DM74LS138 32 mW
  - DM74LS139 34 mW

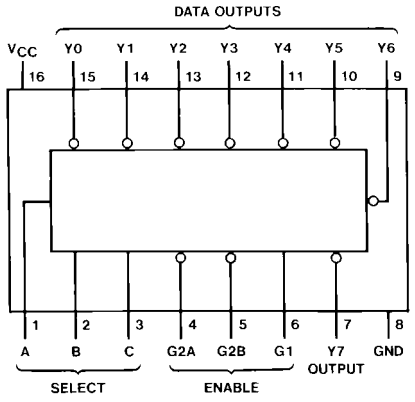
Ordering Code:

Order Number	Package Number	Package Description
DM74LS138M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 Narrow
DM74LS138SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
DM74LS138N	N16E	16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide
DM74LS139M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 Narrow
DM74LS139SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
DM74LS139N	N16E	16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

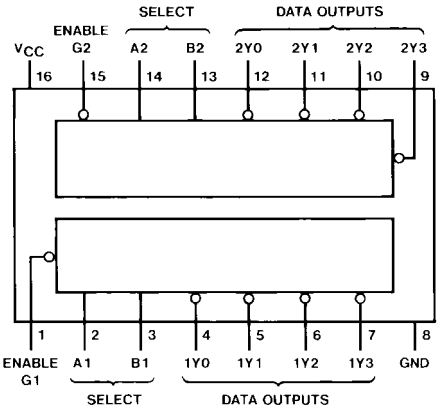
Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagrams

DM74LS138



DM74LS139



Function Tables

DM74LS138

Inputs					Outputs							
Enable		Select										
G1	G2 (Note 1)	C	B	A	YO	Y1	Y2	Y3	Y4	Y5	Y6	Y7
X	H	X	X	X	H	H	H	H	H	H	H	H
L	X	X	X	X	H	H	H	H	H	H	H	H
H	L	L	L	L	L	H	H	H	H	H	H	H
H	L	L	L	H	H	L	H	H	H	H	H	H
H	L	L	H	L	H	H	L	H	H	H	H	H
H	L	L	H	H	H	H	H	L	H	H	H	H
H	L	H	L	L	H	H	H	H	L	H	H	H
H	L	H	L	H	H	H	H	H	H	L	H	H
H	L	H	H	L	H	H	H	H	H	H	L	H
H	L	H	H	H	H	H	H	H	H	H	H	L

DM74LS139

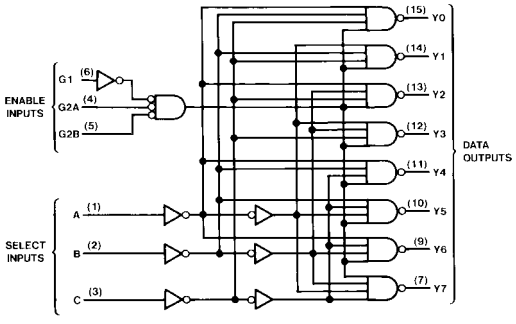
Inputs			Outputs			
Enable	Select					
G	B	A	Y0	Y1	Y2	Y3
H	X	X	H	H	H	H
L	L	L	L	H	H	H
L	L	H	H	L	H	H
L	H	L	H	H	L	H
L	H	H	H	H	H	L

H = HIGH Level
L = LOW Level
X = Don't Care

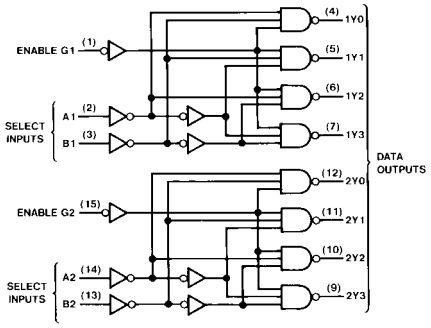
Note 1: G2 = G2A + G2B

Logic Diagrams

DM74LS138



DM74LS139



Absolute Maximum Ratings(Note 2)

Supply Voltage	7V
Input Voltage	7V
Operating Free Air Temperature Range	0°C to +70°C
Storage Temperature Range	−65°C to +150°C

Note 2: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

DM74LS138 Recommended Operating Conditions

Symbol	Parameter	Min	Nom	Max	Units
V_{CC}	Supply Voltage	4.75	5	5.25	V
V_{IH}	HIGH Level Input Voltage	2			V
V_{IL}	LOW Level Input Voltage			0.8	V
I_{OH}	HIGH Level Output Current			−0.4	mA
I_{OL}	LOW Level Output Current			8	mA
T_A	Free Air Operating Temperature	0		70	°C

DM74LS138 Electrical Characteristics

over recommended operating free air temperature range (unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ (Note 3)	Max	Units
V_I	Input Clamp Voltage	V_{CC} = Min, I_I = −18 mA			−1.5	V
V_{OH}	HIGH Level Output Voltage	V_{CC} = Min, I_{OH} = Max, V_{IL} = Max, V_{IH} = Min	2.7	3.4		V
V_{OL}	LOW Level Output Voltage	V_{CC} = Min, I_{OL} = Max, V_{IL} = Max, V_{IH} = Min		0.35	0.5	V
		I_{OL} = 4 mA, V_{CC} = Min		0.25	0.4	
I_I	Input Current @ Max Input Voltage	V_{CC} = Max, V_I = 7V			0.1	mA
I_{IH}	HIGH Level Input Current	V_{CC} = Max, V_I = 2.7V			20	µA
I_{IL}	LOW Level Input Current	V_{CC} = Max, V_I = 0.4V			−0.36	mA
I_{OS}	Short Circuit Output Current	V_{CC} = Max (Note 4)	−20		−100	mA
I_{CC}	Supply Current	V_{CC} = Max (Note 5)		6.3	10	mA

Note 3: All typicals are at V_{CC} = 5V, T_A = 25°C.

Note 4: Not more than one output should be shorted at a time, and the duration should not exceed one second.

Note 5: I_{CC} is measured with all outputs enabled and OPEN.

DM74LS138 Switching Characteristics

at V_{CC} = 5V and T_A = 25°C

Symbol	Parameter	From (Input) To (Output)	Levels of Delay	R_L = 2 kΩ				Units
				C_L = 15 pF		C_L = 50 pF		
				Min	Max	Min	Max	
t_{PLH}	Propagation Delay Time LOW-to-HIGH Level Output	Select to Output	2		18		27	ns
t_{PHL}	Propagation Delay Time HIGH-to-LOW Level Output	Select to Output	2		27		40	ns
t_{PLH}	Propagation Delay Time LOW-to-HIGH Level Output	Select to Output	3		18		27	ns
t_{PHL}	Propagation Delay Time HIGH-to-LOW Level Output	Select to Output	3		27		40	ns
t_{PLH}	Propagation Delay Time LOW-to-HIGH Level Output	Enable to Output	2		18		27	ns
t_{PHL}	Propagation Delay Time HIGH-to-LOW Level Output	Enable to Output	2		24		40	ns
t_{PLH}	Propagation Delay Time LOW-to-HIGH Level Output	Enable to Output	3		18		27	ns
t_{PHL}	Propagation Delay Time HIGH-to-LOW Level Output	Enable to Output	3		28		40	ns

DM74LS139 Recommended Operating Conditions

Symbol	Parameter	Min	Nom	Max	Units
V_{CC}	Supply Voltage	4.75	5	5.25	V
V_{IH}	HIGH Level Input Voltage	2			V
V_{IL}	LOW Level Input Voltage			0.8	V
I_{OH}	HIGH Level Output Current			−0.4	mA
I_{OL}	LOW Level Output Current			8	mA
T_A	Free Air Operating Temperature	0		70	°C

DM74LS139 Electrical Characteristics

over recommended operating free air temperature range (unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ (Note 6)	Max	Units
V_I	Input Clamp Voltage	V_{CC} = Min, I_I = −18 mA			−1.5	V
V_{OH}	HIGH Level Output Voltage	V_{CC} = Min, I_{OH} = Max, V_{IL} = Max, V_{IH} = Min	2.7	3.4		V
V_{OL}	LOW Level Output Voltage	V_{CC} = Min, I_{OL} = Max, V_{IL} = Max, V_{IH} = Min		0.35	0.5	V
		I_{OL} = 4 mA, V_{CC} = Min		0.25	0.4	
I_I	Input Current @ Max Input Voltage	V_{CC} = Max, V_I = 7V			0.1	mA
I_{IH}	HIGH Level Input Current	V_{CC} = Max, V_I = 2.7V			20	µA
I_{IL}	LOW Level Input Current	V_{CC} = Max, V_I = 0.4V			−0.36	mA
I_{OS}	Short Circuit Output Current	V_{CC} = Max (Note 7)	−20		−100	mA
I_{CC}	Supply Current	V_{CC} = Max (Note 8)		6.8	11	mA

Note 6: All typicals are at V_{CC} = 5V, T_A = 25°C.

Note 7: Not more than one output should be shorted at a time, and the duration should not exceed one second.

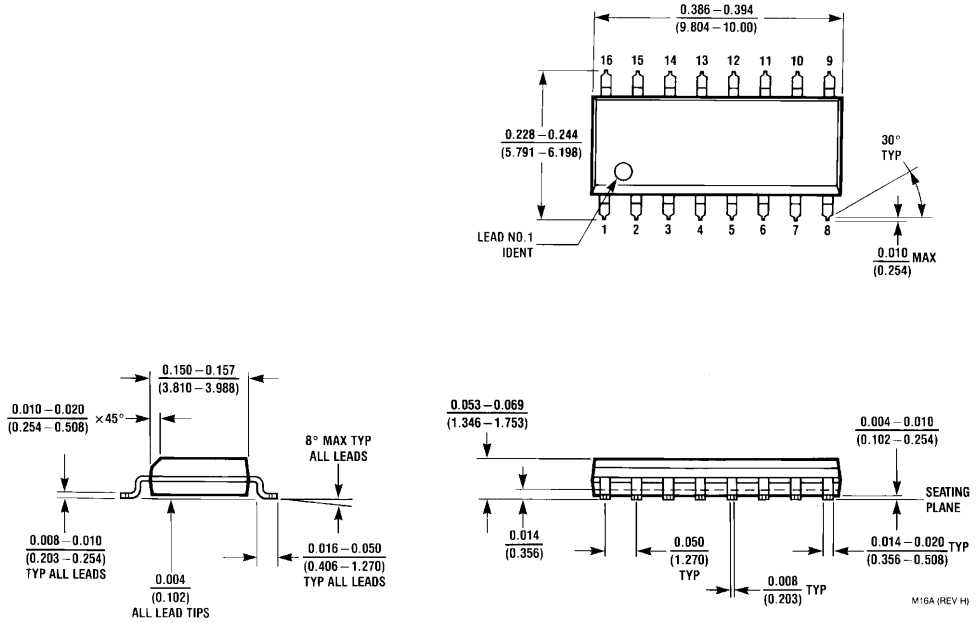
Note 8: I_{CC} is measured with all outputs enabled and OPEN.

DM74LS139 Switching Characteristics

at V_{CC} = 5V and T_A = 25°C

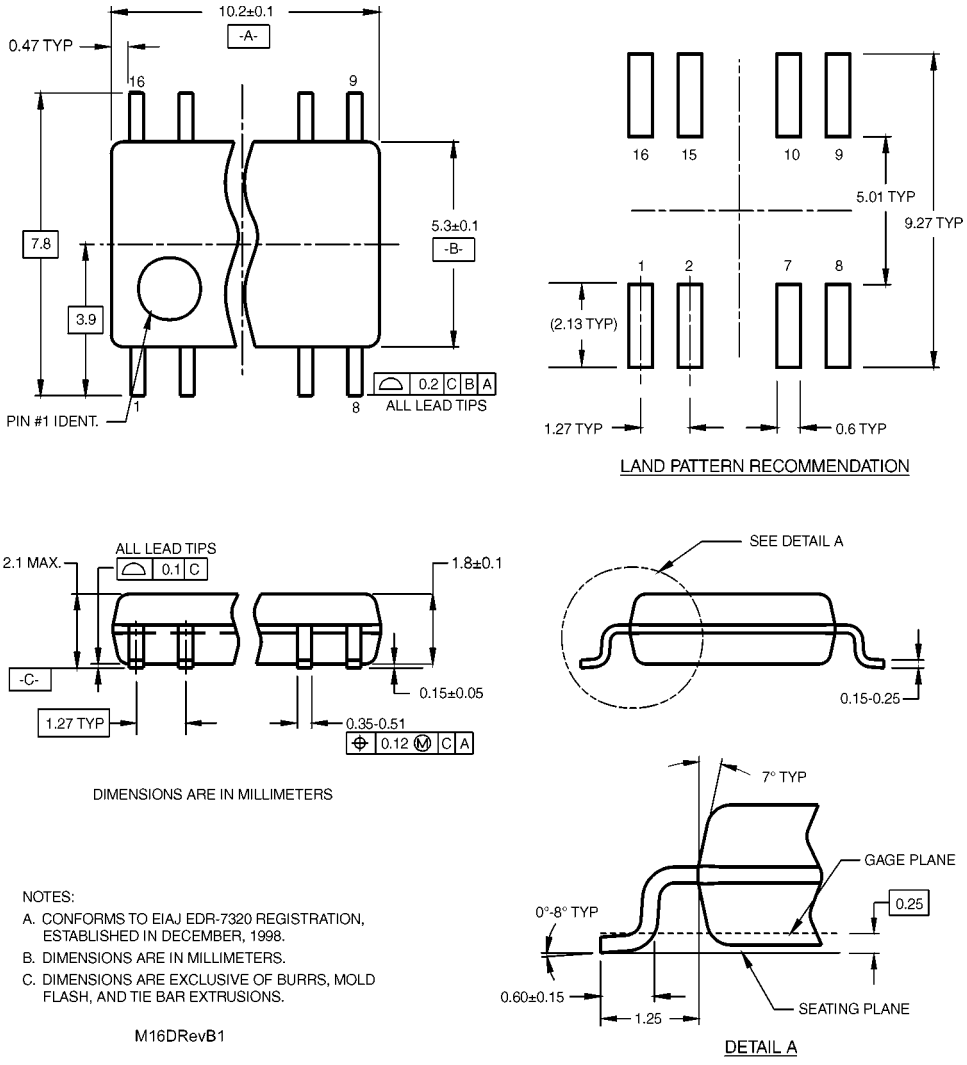
Symbol	Parameter	From (Input) To (Output)	R_L = 2 kΩ				Units
			C_L = 15 pF		C_L = 50 pF		
			Min	Max	Min	Max	
t_{PLH}	Propagation Delay Time LOW-to-HIGH Level Output	Select to Output		18		27	ns
t_{PHL}	Propagation Delay Time HIGH-to-LOW Level Output	Select to Output		27		40	ns
t_{PLH}	Propagation Delay Time LOW-to-HIGH Level Output	Enable to Output		18		27	ns
t_{PHL}	Propagation Delay Time HIGH-to-LOW Level Output	Enable to Output		24		40	ns

Physical Dimensions inches (millimeters) unless otherwise noted



16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 Narrow
Package Number M16A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



NOTES:

A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

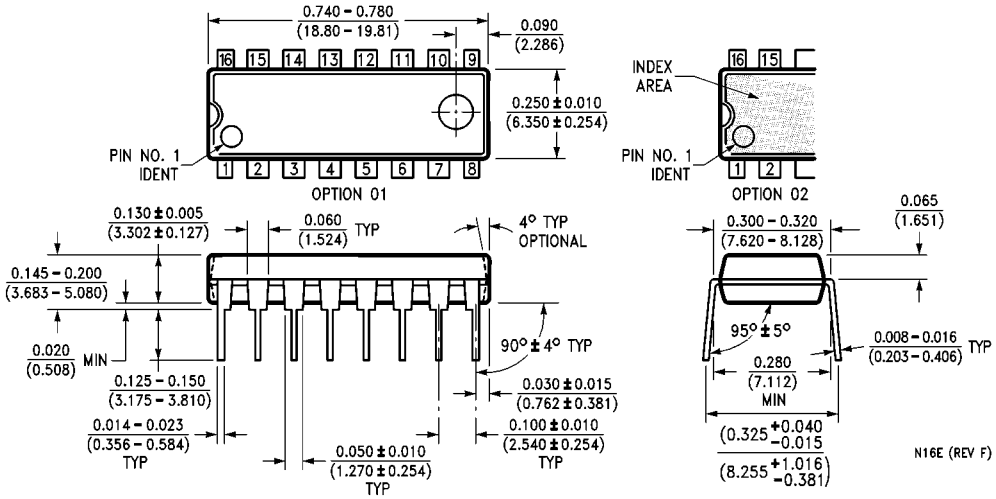
B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M16DRevB1

16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M16D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide
Package Number N16E

SN5432, SN54LS32, SN54S32, SN7432, SN74LS32, SN74S32
QUADRUPLE 2-INPUT POSITIVE-OR GATES

DECEMBER 1983 – REVISED MARCH 1988

- **Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs**
- **Dependable Texas Instruments Quality and Reliability**

description

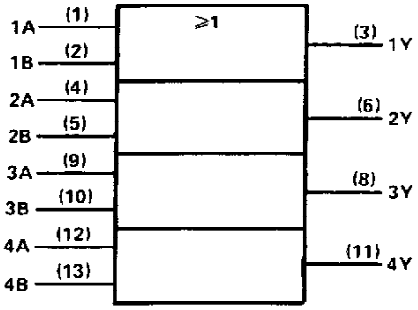
These devices contain four independent 2-input OR gates.

The SN5432, SN54LS32 and SN54S32 are characterized for operation over the full military range of −55°C to 125°C. The SN7432, SN74LS32 and SN74S32 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each gate)

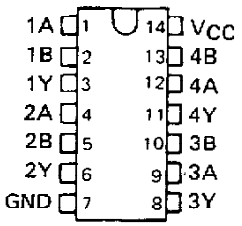
INPUTS		OUTPUT
A	B	Y
H	X	H
X	H	H
L	L	L

logic symbol†

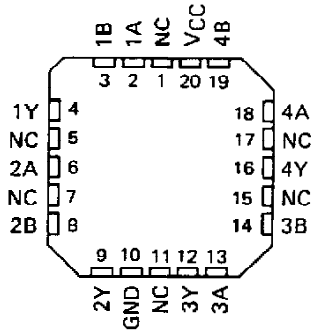


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, or W packages.

SN5432, SN54LS32, SN54S32 . . . J OR W PACKAGE
SN7432 . . . N PACKAGE
SN74LS32, SN74S32 . . . D OR N PACKAGE
(TOP VIEW)

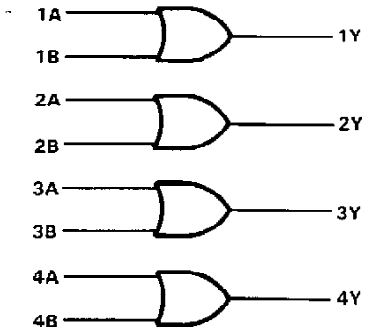


SN54LS32, SN54S32 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

logic diagram

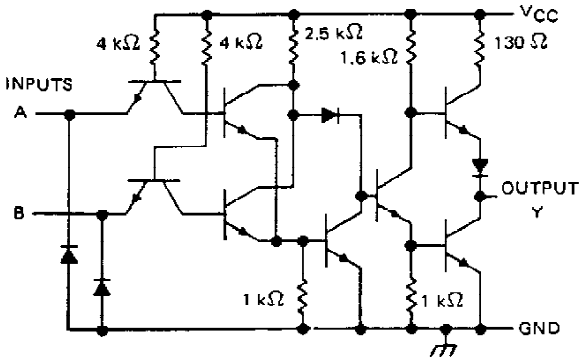


positive logic

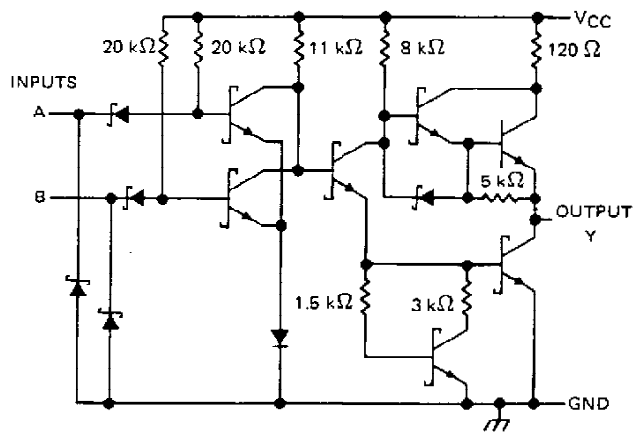
$Y = A + B$ or $Y = \overline{\overline{A} \cdot \overline{B}}$

schematics (each gate)

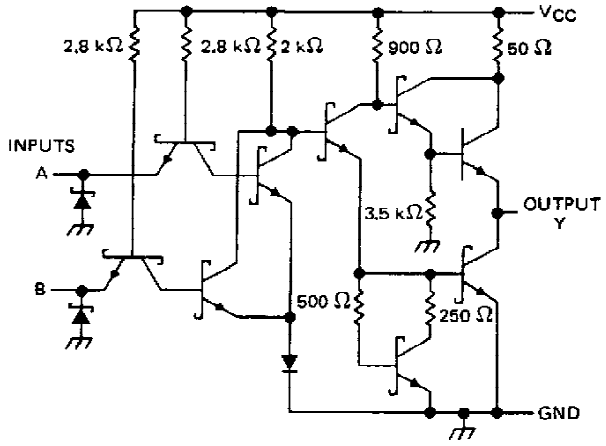
'32



'LS32



'S32



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)		7 V
Input voltage:	'32, 'S32	5.5 V
	'LS32	7 V
Operating free-air temperature:	SN54'	−55°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range		−65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN5432			SN7432			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			−0.8			−0.8	mA
I_{OL}	Low-level output current			16			16	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†			SN5432			SN7432			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN,	I_I = −12 mA				−1.5			−1.5	V
V_{OH}	V_{CC} = MIN,	V_{IH} = 2 V,	I_{OH} = −0.8 mA	2.4	3.4		2.4	3.4		V
V_{OL}	V_{CC} = MIN,	V_{IL} = 0.8 V,	I_{OL} = 16 mA		0.2	0.4		0.2	0.4	V
I_I	V_{CC} = MAX,	V_I = 5.5 V				1			1	mA
I_{IH}	V_{CC} = MAX,	V_I = 2.4 V				40			40	μA
I_{IL}	V_{CC} = MAX,	V_I = 0.4 V				−1.6			−1.6	mA
I_{OS}§	V_{CC} = MAX			−20		−55	−18		−55	mA
I_{CCH}	V_{CC} = MAX,	See Note 2			15	22		15	22	mA
I_{CCL}	V_{CC} = MAX,	V_I = 0 V			23	38		23	38	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time.
NOTE 2: One input at 4.5 V, all others at GND.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	A or B	Y	R_L = 400 Ω,	C_L = 15 pF		10	15	ns
t_{PHL}						14	22	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

		SN54LS32			SN74LS32			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
I_{OH}	High-level output current			−0.4			−0.4	mA
I_{OL}	Low-level output current			4			8	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †			SN54LS32			SN74LS32			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN,	I_I = −18 mA				−1.5			−1.5	V
V_{OH}	V_{CC} = MIN,	V_{IH} = 2 V,	I_{OH} = −0.4 mA	2.5	3.4		2.7	3.4		V
V_{OL}	V_{CC} = MIN,	V_{IL} = MAX,	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
	V_{CC} = MIN,	V_{IL} = MAX,	I_{OL} = 8 mA					0.35	0.5	
I_I	V_{CC} = MAX,	V_I = 7 V				0.1			0.1	mA
I_{IH}	V_{CC} = MAX,	V_I = 2.7 V				20			20	μA
I_{IL}	V_{CC} = MAX,	V_I = 0.4 V				−0.4			−0.4	mA
I_{OS}§	V_{CC} = MAX			−20		−100	−20		−100	mA
I_{CCH}	V_{CC} = MAX,	See Note 2			3.1	6.2		3.1	6.2	mA
I_{CCL}	V_{CC} = MAX,	V_I = 0 V			4.9	9.8		4.9	9.8	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.
NOTE 2: One input at 4.5 V, all others at GND.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	A or B	Y	R_L = 2 kΩ,	C_L = 15 pF		14	22	ns
t_{PHL}						14	22	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

		SN54S32			SN74S32			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			−1			−1	mA
I_{OL}	Low-level output current			20			20	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †			SN54S32			SN74S32			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN,	I_I = −18 mA				−1.2			−1.2	V
V_{OH}	V_{CC} = MIN,	V_{IH} = 2 V,	I_{OH} = −1 mA	2.5	3.4		2.7	3.4		V
V_{OL}	V_{CC} = MIN,	V_{IL} = 0.8 V,	I_{OL} = 20 mA			0.5			0.5	V
I_I	V_{CC} = MAX,	V_I = 5.5 V				1			1	mA
I_{IH}	V_{CC} = MAX,	V_I = 2.7 V				50			50	μA
I_{IL}	V_{CC} = MAX,	V_I = 0.5 V				−2			−2	mA
I_{OS} §	V_{CC} = MAX			−40		−100	−40		−100	mA
I_{CCH}	V_{CC} = MAX,	See Note 2			18	32		18	32	mA
I_{CCL}	V_{CC} = MAX,	V_I = 0 V			38	68		38	68	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.
NOTE 2: One input at 4.5 V, all others at GND.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	A or B	Y	R_L = 280 Ω,	C_L = 15 pF		4	7	ns
t_{PHL}						4	7	ns
t_{PLH}	A or B	Y	R_L = 280 Ω,	C_L = 50 pF		5		ns
t_{PHL}						5		ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
5962-9557401QCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9557401QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
5962-9557401QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30501B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30501B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30501BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30501BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30501SCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30501SCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30501SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30501SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN5432J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN5432J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS32J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS32J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54S32J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54S32J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN7432N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN7432N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN7432N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7432N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7432NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN7432NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS32D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32DG4	ACTIVE	SOIC	D	14	50	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
						no Sb/Br)		
SN74LS32DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS32J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS32N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS32N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS32N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS32N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS32NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS32NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS32NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS32NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S32D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S32D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S32DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S32DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S32DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S32DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S32DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S32DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN74S32N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S32N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S32N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S32N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S32NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S32NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S32NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S32NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S32NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S32NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ5432J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5432J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5432W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ5432W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS32FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS32FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS32J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS32J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS32W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS32W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S32FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S32FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S32J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54S32J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54S32W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S32W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS

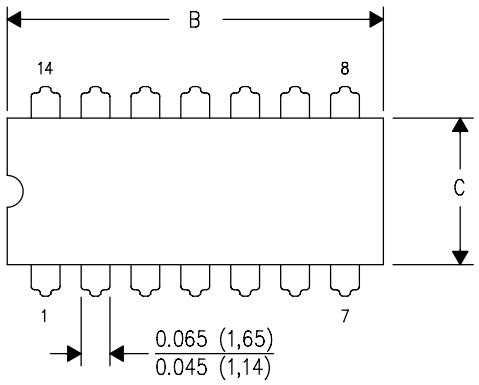
compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

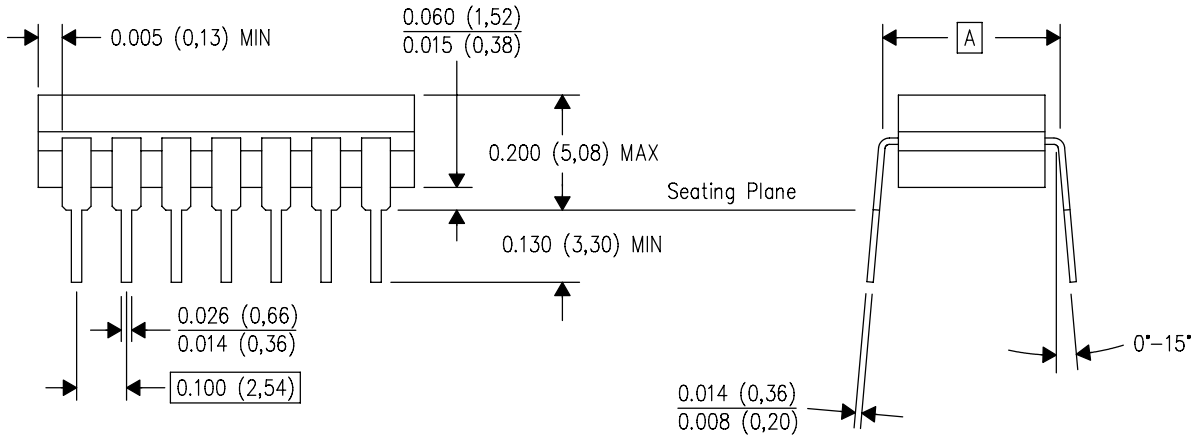
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



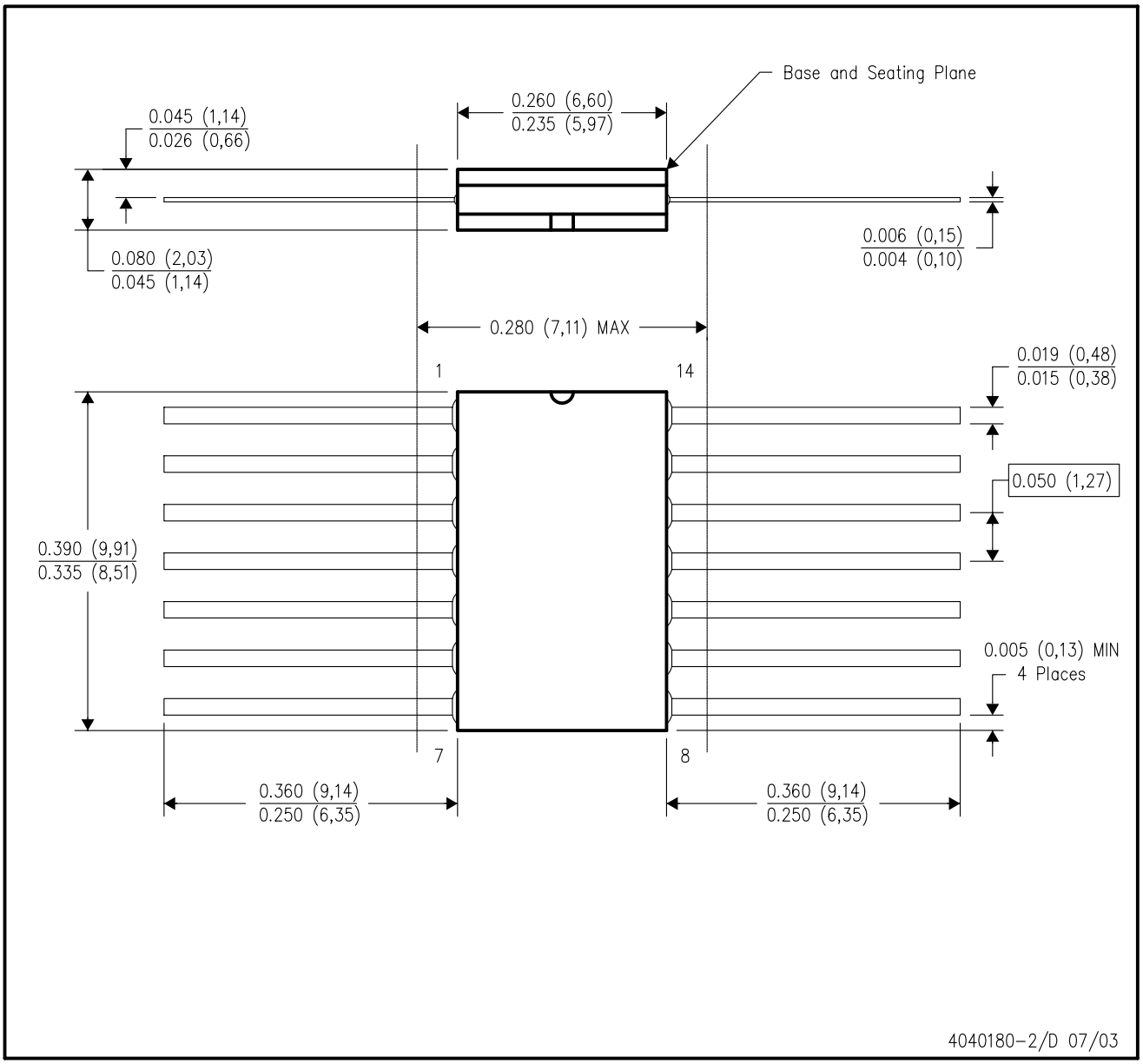
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

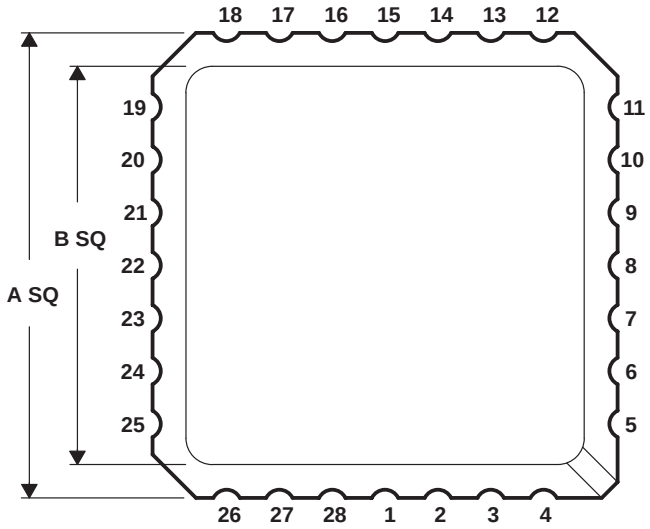
W (R–GDFP–F14) CERAMIC DUAL FLATPACK



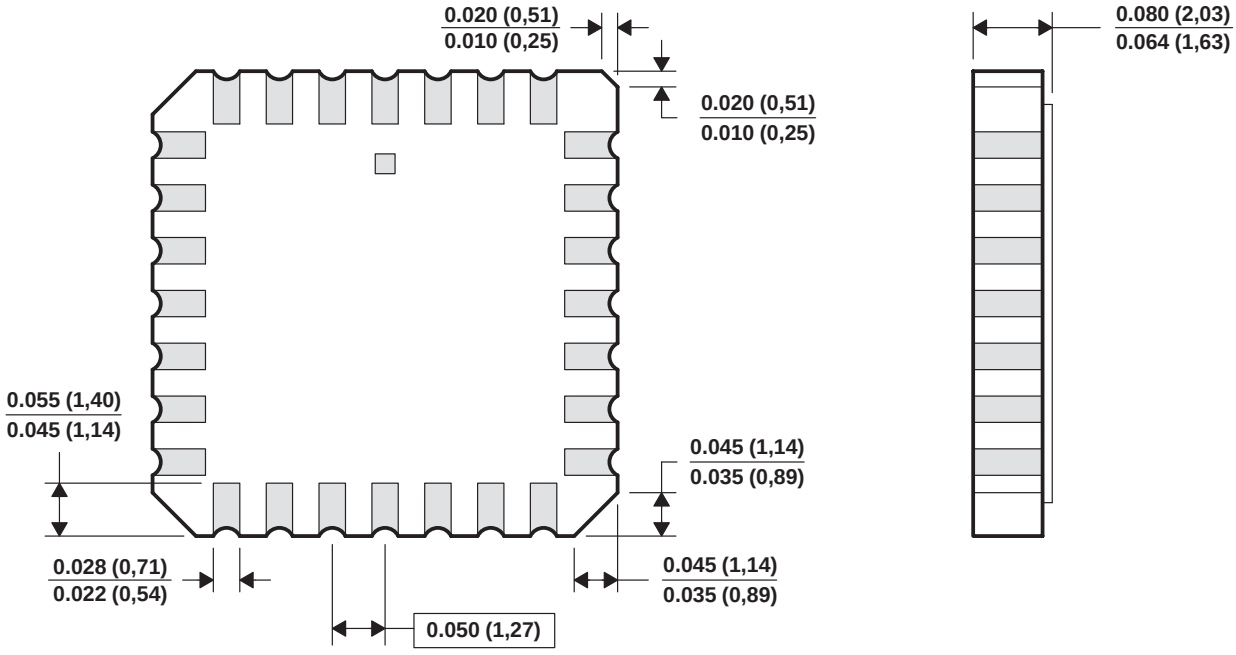
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14 and JEDEC MO–092AB

FK (S-CQCC-N)** **LEADLESS CERAMIC CHIP CARRIER**

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



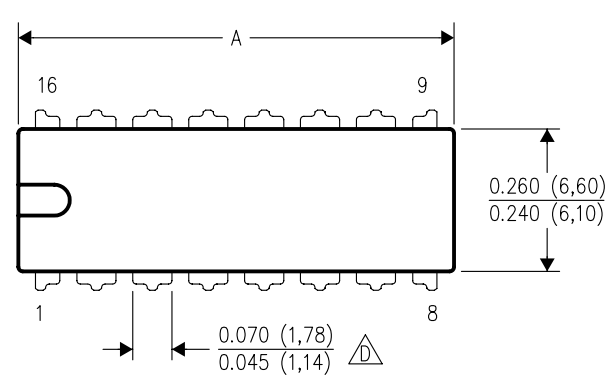
4040140/D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

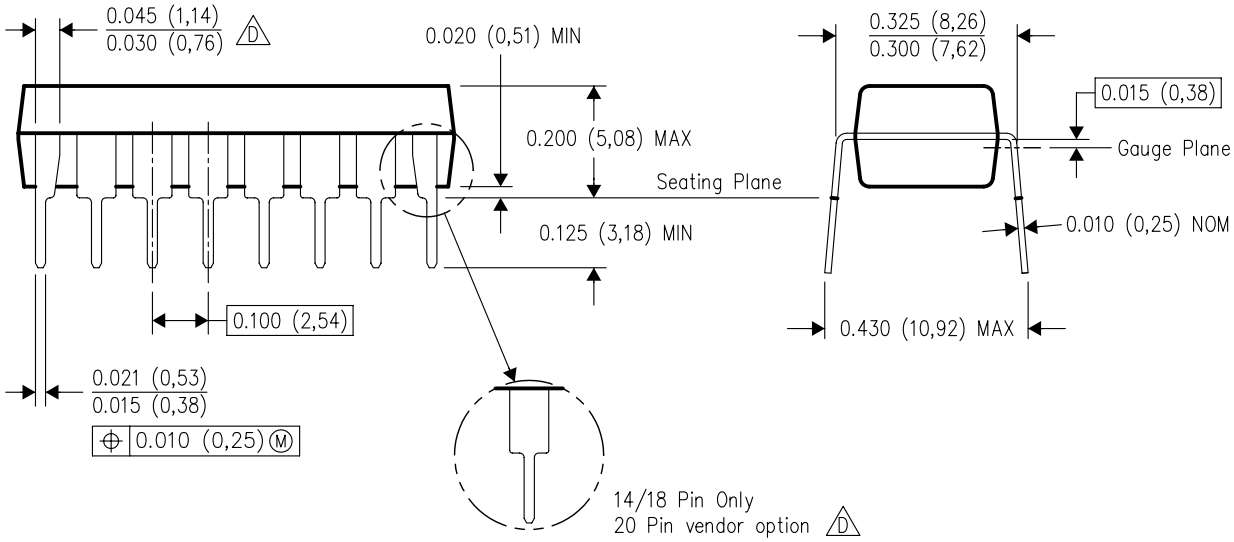
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



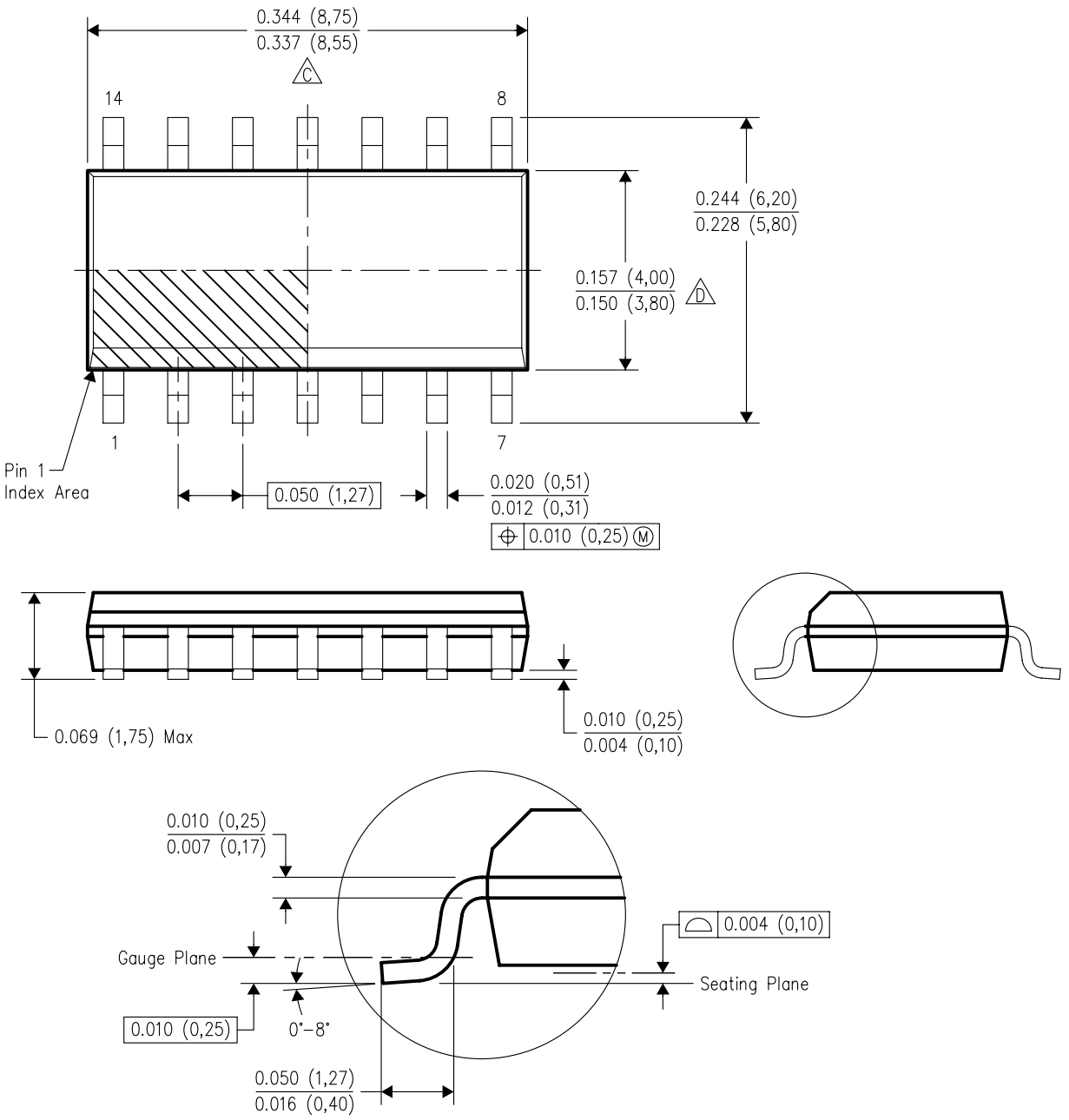
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G14) PLASTIC SMALL–OUTLINE PACKAGE

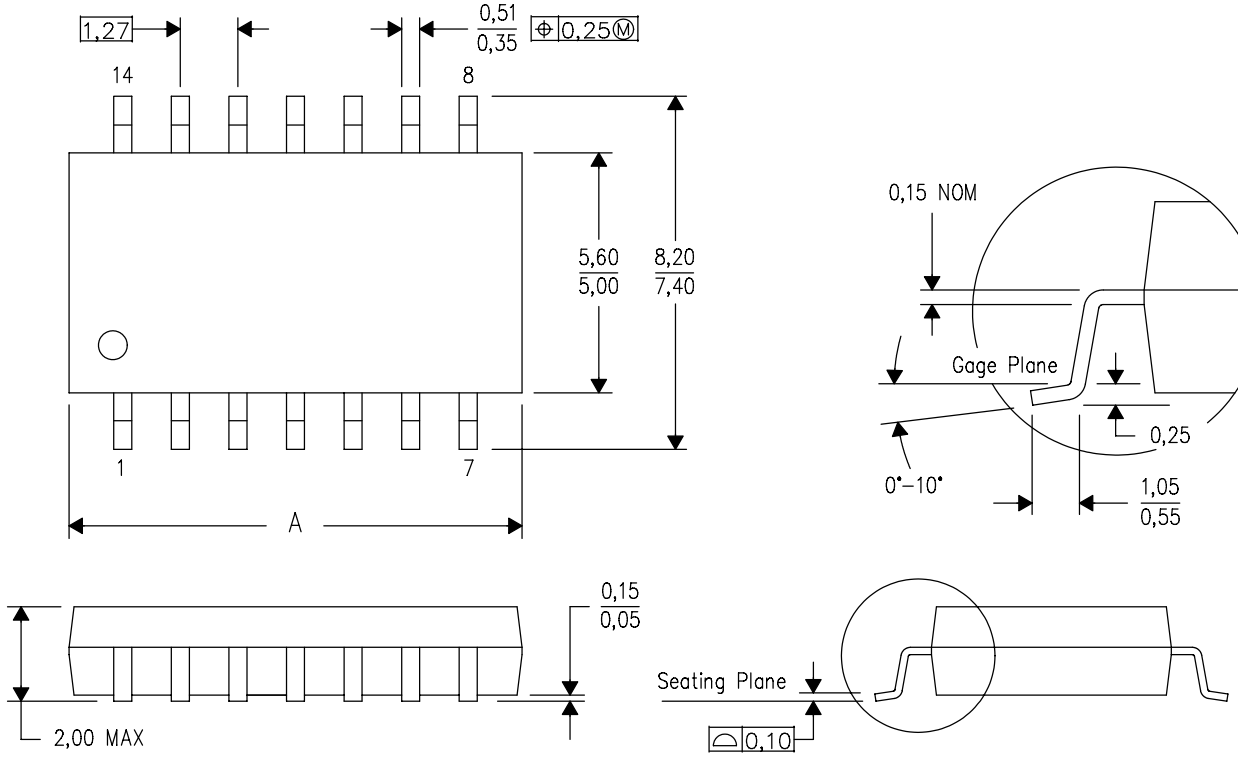


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AB.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

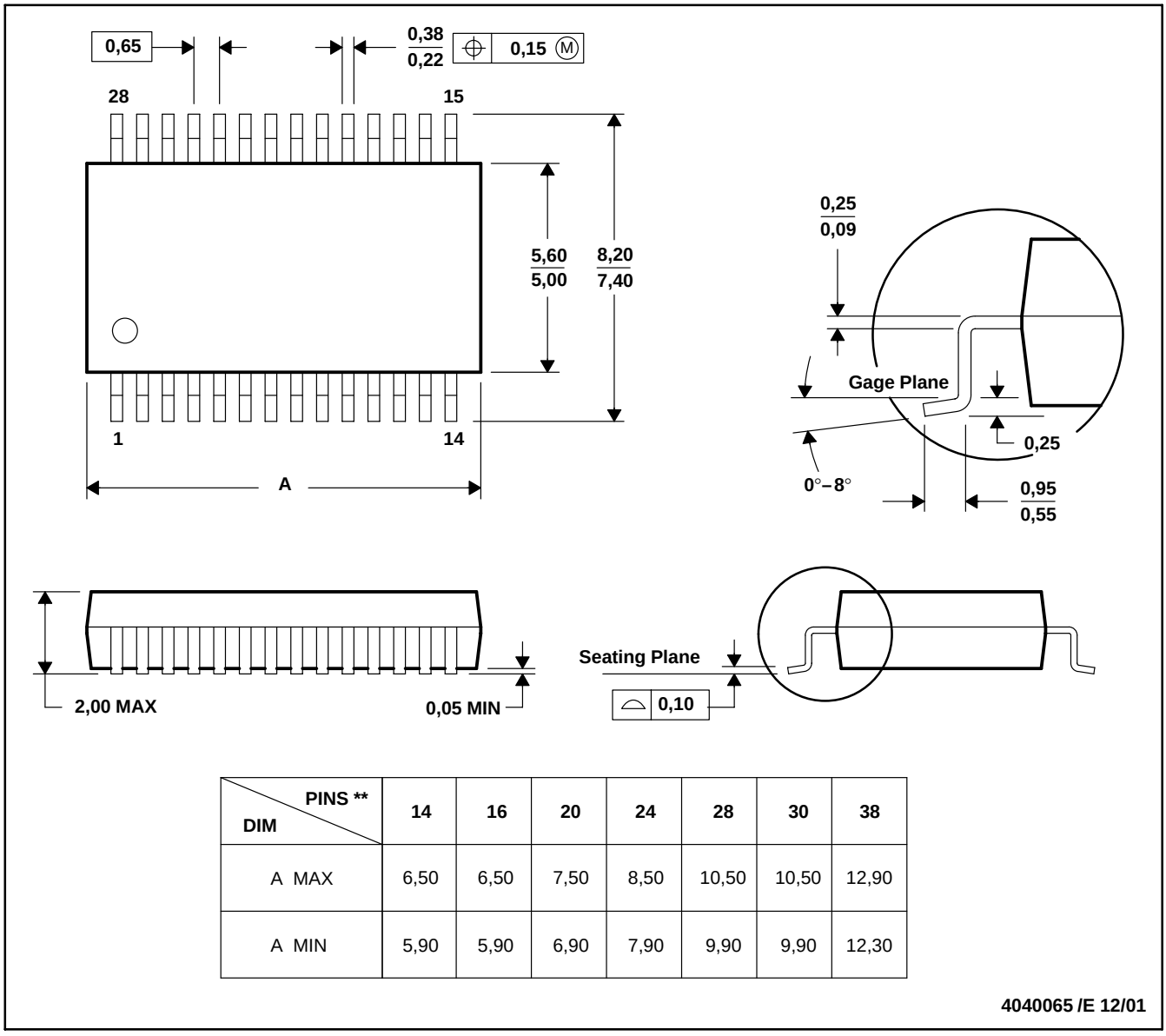
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

MSSO002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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National Semiconductor

July 2006

LM555 Timer

General Description

The LM555 is a highly stable device for generating accurate time delays or oscillation. Additional terminals are provided for triggering or resetting if desired. In the time delay mode of operation, the time is precisely controlled by one external resistor and capacitor. For astable operation as an oscillator, the free running frequency and duty cycle are accurately controlled with two external resistors and one capacitor. The circuit may be triggered and reset on falling waveforms, and the output circuit can source or sink up to 200mA or drive TTL circuits.

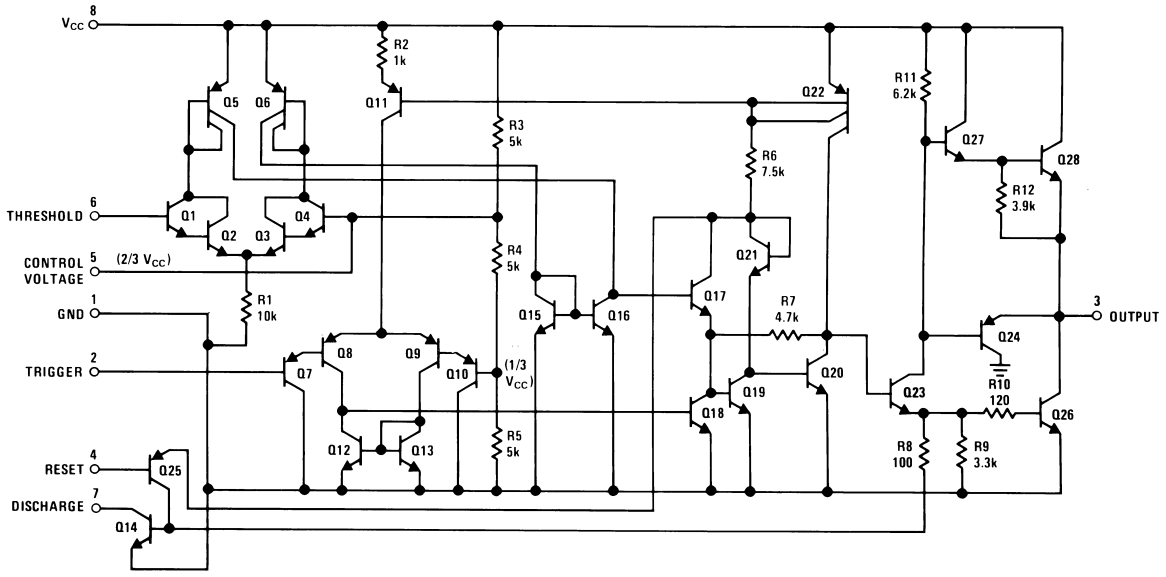
Features

- Direct replacement for SE555/NE555
- Timing from microseconds through hours
- Operates in both astable and monostable modes
- Adjustable duty cycle
- Output can source or sink 200 mA
- Output and supply TTL compatible
- Temperature stability better than 0.005% per ˚C
- Normally on and normally off output
- Available in 8-pin MSOP package

Applications

- Precision timing
- Pulse generation
- Sequential timing
- Time delay generation
- Pulse width modulation
- Pulse position modulation
- Linear ramp generator

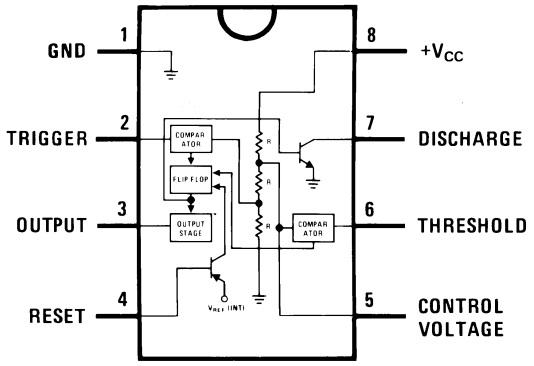
Schematic Diagram



00785101

Connection Diagram

Dual-In-Line, Small Outline and Molded Mini Small Outline Packages



00785103

Top View

Ordering Information

Package	Part Number	Package Marking	Media Transport	NSC Drawing
8-Pin SOIC	LM555CM	LM555CM	Rails	M08A
	LM555CMX	LM555CM	2.5k Units Tape and Reel	
8-Pin MSOP	LM555CMM	Z55	1k Units Tape and Reel	MUA08A
	LM555CMMX	Z55	3.5k Units Tape and Reel	
8-Pin MDIP	LM555CN	LM555CN	Rails	N08E

Absolute Maximum Ratings (Note 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage	+18V
Power Dissipation (Note 3)	
LM555CM, LM555CN	1180 mW
LM555CMM	613 mW
Operating Temperature Ranges	
LM555C	0˚C to +70˚C
Storage Temperature Range	−65˚C to +150˚C

Soldering Information

Dual-In-Line Package	
Soldering (10 Seconds)	260˚C
Small Outline Packages	
(SOIC and MSOP)	
Vapor Phase (60 Seconds)	215˚C
Infrared (15 Seconds)	220˚C

See AN-450 “Surface Mounting Methods and Their Effect on Product Reliability” for other methods of soldering surface mount devices.

Electrical Characteristics (Notes 1, 2)

(T_A = 25˚C, V_{CC} = +5V to +15V, unless othewise specified)

Parameter	Conditions	Limits			Units
		LM555C			
		Min	Typ	Max	
Supply Voltage		4.5		16	V
Supply Current	V_{CC} = 5V, R_L = ∞		3	6	
	V_{CC} = 15V, R_L = ∞ (Low State) (Note 4)		10	15	mA
Timing Error, Monostable					
Initial Accuracy			1		%
Drift with Temperature	R_A = 1k to 100kΩ, C = 0.1µF, (Note 5)		50		ppm/˚C
Accuracy over Temperature			1.5		%
Drift with Supply			0.1		%/V
Timing Error, Astable					
Initial Accuracy			2.25		%
Drift with Temperature	R_A, R_B = 1k to 100kΩ, C = 0.1µF, (Note 5)		150		ppm/˚C
Accuracy over Temperature			3.0		%
Drift with Supply			0.30		%/V
Threshold Voltage			0.667		x V_{CC}
Trigger Voltage	V_{CC} = 15V		5		V
	V_{CC} = 5V		1.67		V
Trigger Current			0.5	0.9	µA
Reset Voltage		0.4	0.5	1	V
Reset Current			0.1	0.4	mA
Threshold Current	(Note 6)		0.1	0.25	µA
Control Voltage Level	V_{CC} = 15V	9	10	11	V
	V_{CC} = 5V	2.6	3.33	4	
Pin 7 Leakage Output High			1	100	nA
Pin 7 Sat (Note 7)					
Output Low	V_{CC} = 15V, I_7 = 15mA		180		mV
Output Low	V_{CC} = 4.5V, I_7 = 4.5mA		80	200	mV

Electrical Characteristics (Notes 1, 2) (Continued)

(T_A = 25˚C, V_{CC} = +5V to +15V, unless othewise specified)

Parameter	Conditions	Limits			Units
		LM555C			
		Min	Typ	Max	
Output Voltage Drop (Low)	V_{CC} = 15V				
	I_{SINK} = 10mA		0.1	0.25	V
	I_{SINK} = 50mA		0.4	0.75	V
	I_{SINK} = 100mA		2	2.5	V
	I_{SINK} = 200mA		2.5		V
	V_{CC} = 5V				
	I_{SINK} = 8mA				V
	I_{SINK} = 5mA		0.25	0.35	V
Output Voltage Drop (High)	I_{SOURCE} = 200mA, V_{CC} = 15V		12.5		V
	I_{SOURCE} = 100mA, V_{CC} = 15V	12.75	13.3		V
	V_{CC} = 5V	2.75	3.3		V
Rise Time of Output			100		ns
Fall Time of Output			100		ns

Note 1: All voltages are measured with respect to the ground pin, unless otherwise specified.

Note 2: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which guarantee specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not guaranteed for parameters where no limit is given, however, the typical value is a good indication of device performance.

Note 3: For operating at elevated temperatures the device must be derated above 25˚C based on a +150˚C maximum junction temperature and a thermal resistance of 106˚C/W (DIP), 170˚C/W (S0-8), and 204˚C/W (MSOP) junction to ambient.

Note 4: Supply current when output high typically 1 mA less at V_{CC} = 5V.

Note 5: Tested at V_{CC} = 5V and V_{CC} = 15V.

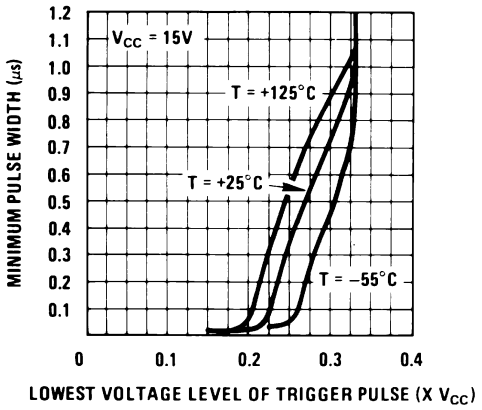
Note 6: This will determine the maximum value of $R_A + R_B$ for 15V operation. The maximum total ($R_A + R_B$) is 20MΩ.

Note 7: No protection against excessive pin 7 current is necessary providing the package dissipation rating will not be exceeded.

Note 8: Refer to RETS555X drawing of military LM555H and LM555J versions for specifications.

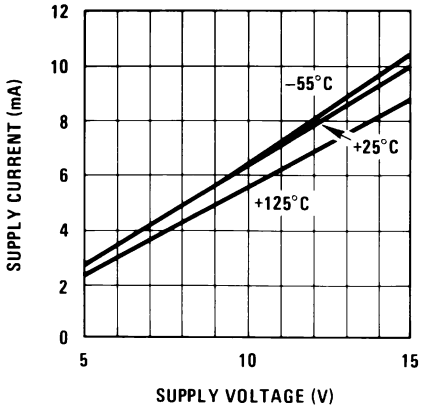
Typical Performance Characteristics

Minimuim Pulse Width Required for Triggering



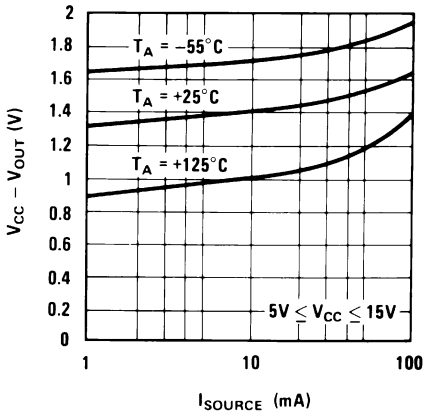
00785104

Supply Current vs. Supply Voltage



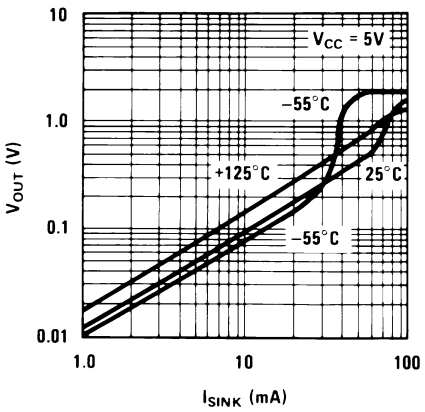
00785119

High Output Voltage vs. Output Source Current



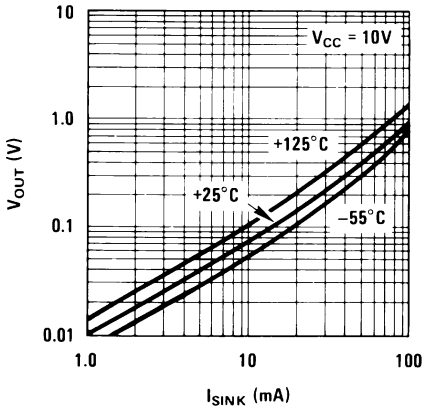
00785120

Low Output Voltage vs. Output Sink Current



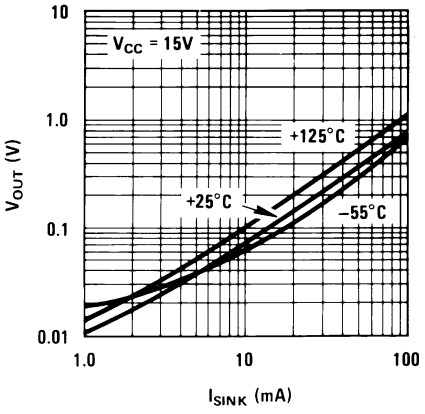
00785121

Low Output Voltage vs. Output Sink Current



00785122

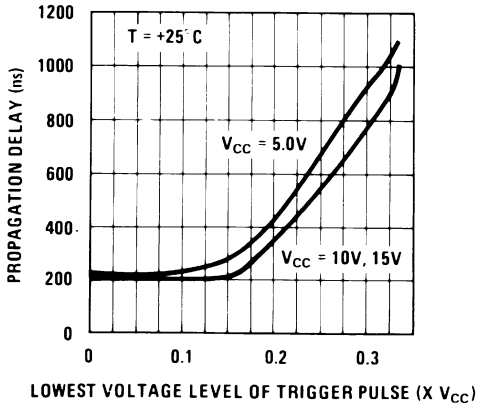
Low Output Voltage vs. Output Sink Current



00785123

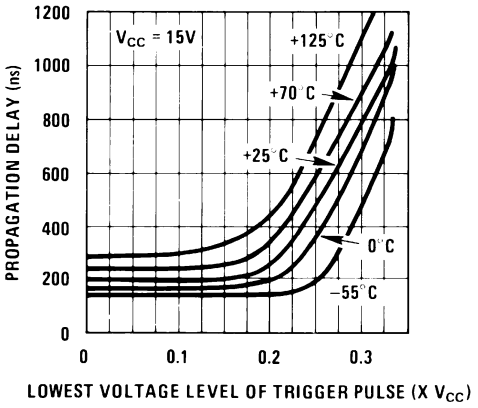
Typical Performance Characteristics (Continued)

Output Propagation Delay vs. Voltage Level of Trigger Pulse



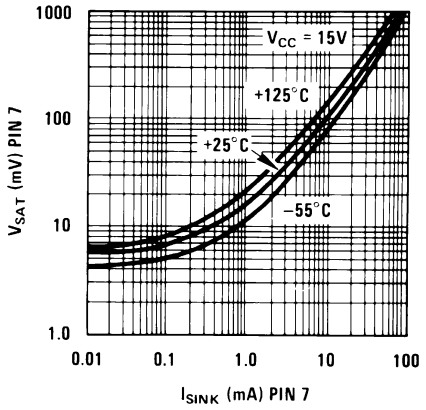
00785124

Output Propagation Delay vs. Voltage Level of Trigger Pulse



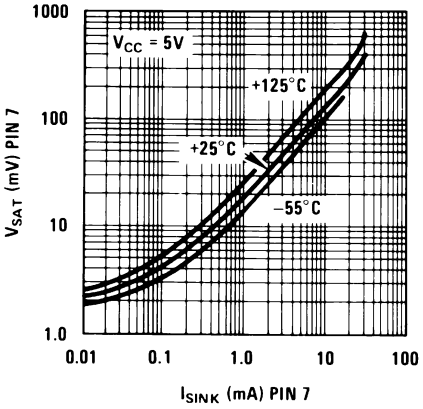
00785125

Discharge Transistor (Pin 7) Voltage vs. Sink Current



00785126

Discharge Transistor (Pin 7) Voltage vs. Sink Current



00785127

Applications Information

MONOSTABLE OPERATION

In this mode of operation, the timer functions as a one-shot (*Figure 1*). The external capacitor is initially held discharged by a transistor inside the timer. Upon application of a negative trigger pulse of less than 1/3 V_{CC} to pin 2, the flip-flop is set which both releases the short circuit across the capacitor and drives the output high.

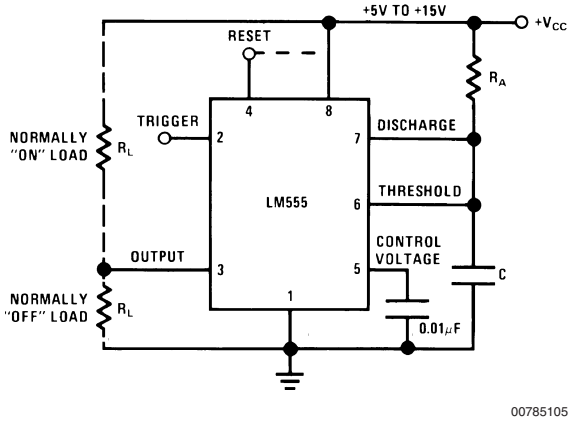
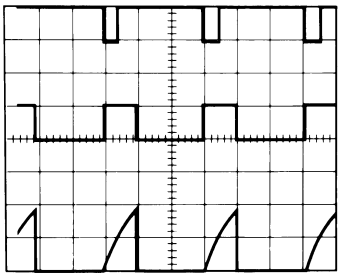


FIGURE 1. Monostable

The voltage across the capacitor then increases exponentially for a period of t = 1.1 R_A C, at the end of which time the voltage equals 2/3 V_{CC}. The comparator then resets the flip-flop which in turn discharges the capacitor and drives the output to its low state. *Figure 2* shows the waveforms generated in this mode of operation. Since the charge and the threshold level of the comparator are both directly proportional to supply voltage, the timing interval is independent of supply.



V_{CC} = 5V Top Trace: Input 5V/Div.
TIME = 0.1 ms/DIV. Middle Trace: Output 5V/Div.
R_A = 9.1kΩ Bottom Trace: Capacitor Voltage 2V/Div.
C = 0.01μF

FIGURE 2. Monostable Waveforms

During the timing cycle when the output is high, the further application of a trigger pulse will not effect the circuit so long as the trigger input is returned high at least 10μs before the end of the timing interval. However the circuit can be reset during this time by the application of a negative pulse to the reset terminal (pin 4). The output will then remain in the low state until a trigger pulse is again applied.

When the reset function is not in use, it is recommended that it be connected to V_{CC} to avoid any possibility of false triggering.

Figure 3 is a nomograph for easy determination of R, C values for various time delays.

NOTE: In monostable operation, the trigger should be driven high before the end of timing cycle.

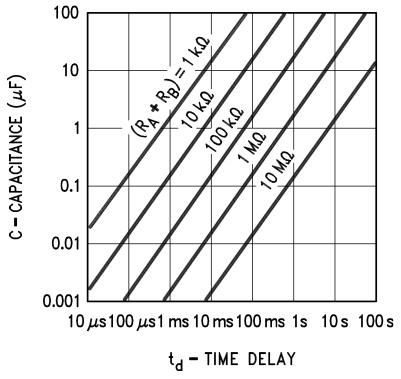


FIGURE 3. Time Delay

ASTABLE OPERATION

If the circuit is connected as shown in *Figure 4* (pins 2 and 6 connected) it will trigger itself and free run as a multivibrator. The external capacitor charges through R_A + R_B and discharges through R_B. Thus the duty cycle may be precisely set by the ratio of these two resistors.

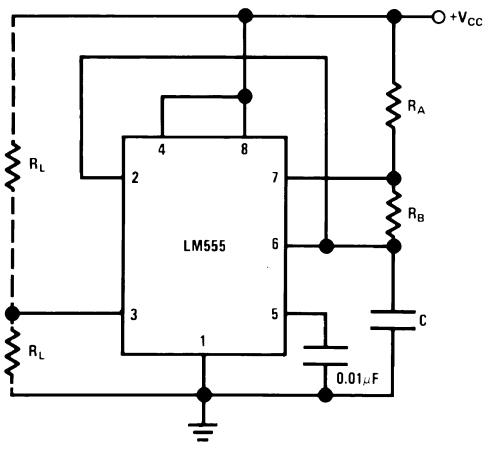
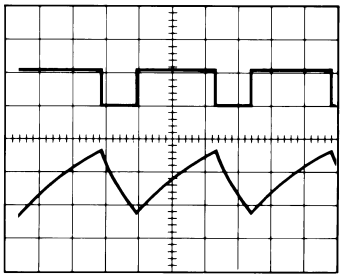


FIGURE 4. Astable

In this mode of operation, the capacitor charges and discharges between 1/3 V_{CC} and 2/3 V_{CC}. As in the triggered mode, the charge and discharge times, and therefore the frequency are independent of the supply voltage.

Applications Information (Continued)

Figure 5 shows the waveforms generated in this mode of operation.



00785109

V_{CC} = 5V Top Trace: Output 5V/Div.
TIME = 20µs/DIV. Bottom Trace: Capacitor Voltage 1V/Div.
R_A = 3.9kΩ
R_B = 3kΩ
C = 0.01µF

FIGURE 5. Astable Waveforms

The charge time (output high) is given by:

$$t_1 = 0.693\ (R_A + R_B)\ C$$

And the discharge time (output low) by:

$$t_2 = 0.693\ (R_B)\ C$$

Thus the total period is:

$$T = t_1 + t_2 = 0.693\ (R_A + 2R_B)\ C$$

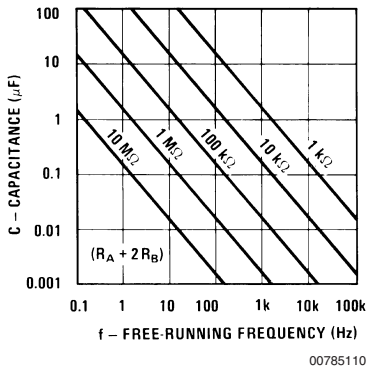
The frequency of oscillation is:

$$f = \frac{1}{T} = \frac{1.44}{(R_A + 2R_B)\ C}$$

Figure 6 may be used for quick determination of these RC values.

The duty cycle is:

$$D = \frac{R_B}{R_A + 2R_B}$$

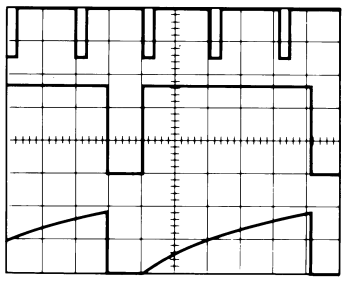


00785110

FIGURE 6. Free Running Frequency

FREQUENCY DIVIDER

The monostable circuit of *Figure 1* can be used as a frequency divider by adjusting the length of the timing cycle. *Figure 7* shows the waveforms generated in a divide by three circuit.



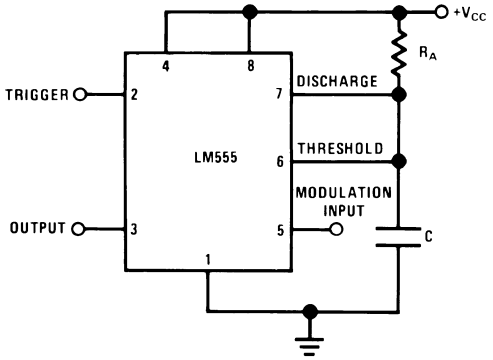
00785111

V_{CC} = 5V Top Trace: Input 4V/Div.
TIME = 20µs/DIV. Middle Trace: Output 2V/Div.
R_A = 9.1kΩ Bottom Trace: Capacitor 2V/Div.
C = 0.01µF

FIGURE 7. Frequency Divider

PULSE WIDTH MODULATOR

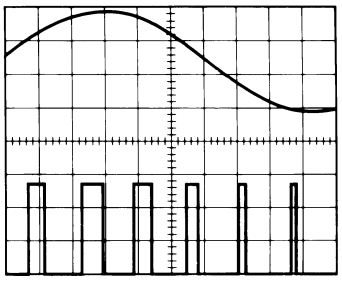
When the timer is connected in the monostable mode and triggered with a continuous pulse train, the output pulse width can be modulated by a signal applied to pin 5. *Figure 8* shows the circuit, and in *Figure 9* are some waveform examples.



00785112

FIGURE 8. Pulse Width Modulator

Applications Information (Continued)



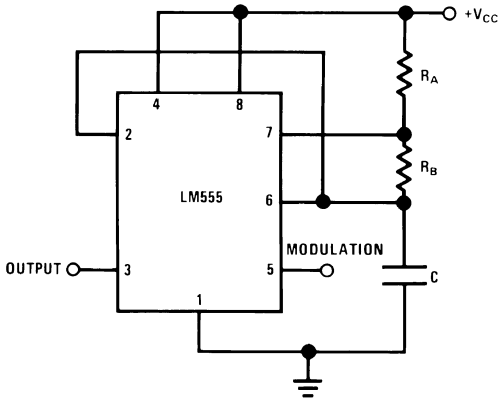
00785113

V_{CC} = 5V Top Trace: Modulation 1V/Div.
TIME = 0.2 ms/DIV. Bottom Trace: Output Voltage 2V/Div.
R_A = 9.1kΩ
C = 0.01µF

FIGURE 9. Pulse Width Modulator

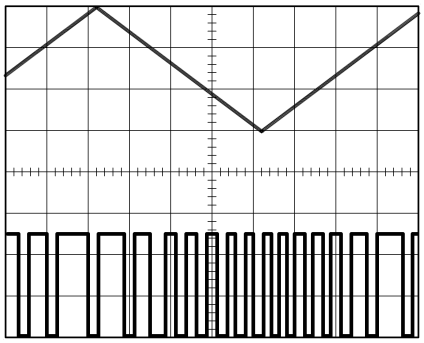
PULSE POSITION MODULATOR

This application uses the timer connected for astable operation, as in *Figure 10*, with a modulating signal again applied to the control voltage terminal. The pulse position varies with the modulating signal, since the threshold voltage and hence the time delay is varied. *Figure 11* shows the waveforms generated for a triangle wave modulation signal.



00785114

FIGURE 10. Pulse Position Modulator



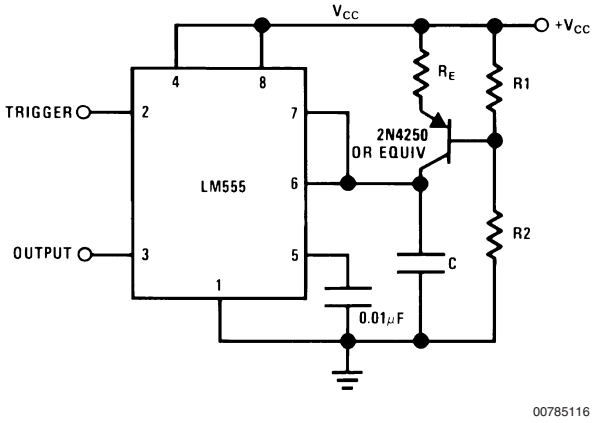
00785115

V_{CC} = 5V Top Trace: Modulation Input 1V/Div.
TIME = 0.1 ms/DIV. Bottom Trace: Output 2V/Div.
R_A = 3.9kΩ
R_B = 3kΩ
C = 0.01µF

FIGURE 11. Pulse Position Modulator

LINEAR RAMP

When the pullup resistor, R_A, in the monostable circuit is replaced by a constant current source, a linear ramp is generated. *Figure 12* shows a circuit configuration that will perform this function.



00785116

FIGURE 12.

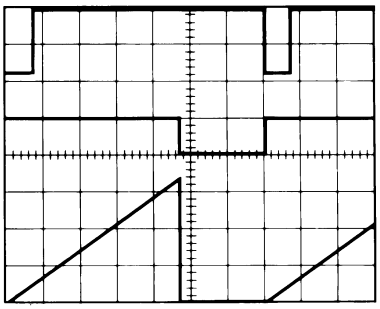
Figure 13 shows waveforms generated by the linear ramp. The time interval is given by:

$$T = \frac{2/3\ V_{CC}\ R_E\ (R_1 + R_2)\ C}{R_1\ V_{CC} - V_{BE}\ (R_1 + R_2)}$$

$$V_{BE} \cong 0.6V$$

$$V_{BE} \simeq 0.6V$$

Applications Information (Continued)



00785117

V_{CC} = 5V Top Trace: Input 3V/Div.
TIME = 20µs/DIV. Middle Trace: Output 5V/Div.
R_1 = 47kΩ Bottom Trace: Capacitor Voltage 1V/Div.
R_2 = 100kΩ
R_E = 2.7 kΩ
C = 0.01 µF

FIGURE 13. Linear Ramp

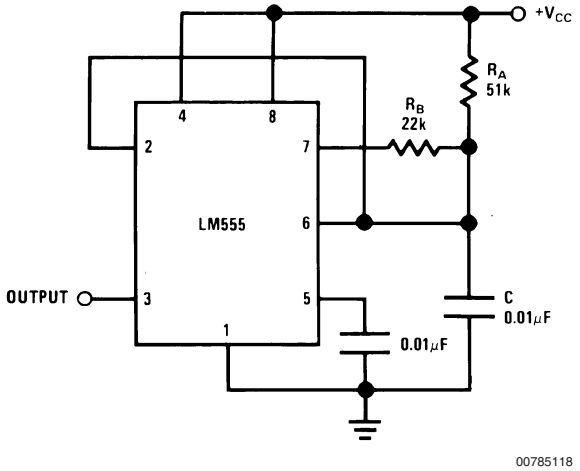
50% DUTY CYCLE OSCILLATOR

For a 50% duty cycle, the resistors R_A and R_B may be connected as in *Figure 14*. The time period for the output high is the same as previous, $t_1 = 0.693\ R_A\ C$. For the output low it is t_2 =

$$\left[(R_A\ R_B)/(R_A + R_B)\right] C\ \ell n \left[\frac{R_B - 2R_A}{2R_B - R_A}\right]$$

Thus the frequency of oscillation is

$$f = \frac{1}{t_1 + t_2}$$



00785118

FIGURE 14. 50% Duty Cycle Oscillator

Note that this circuit will not oscillate if R_B is greater than 1/2 R_A because the junction of R_A and R_B cannot bring pin 2 down to 1/3 V_{CC} and trigger the lower comparator.

ADDITIONAL INFORMATION

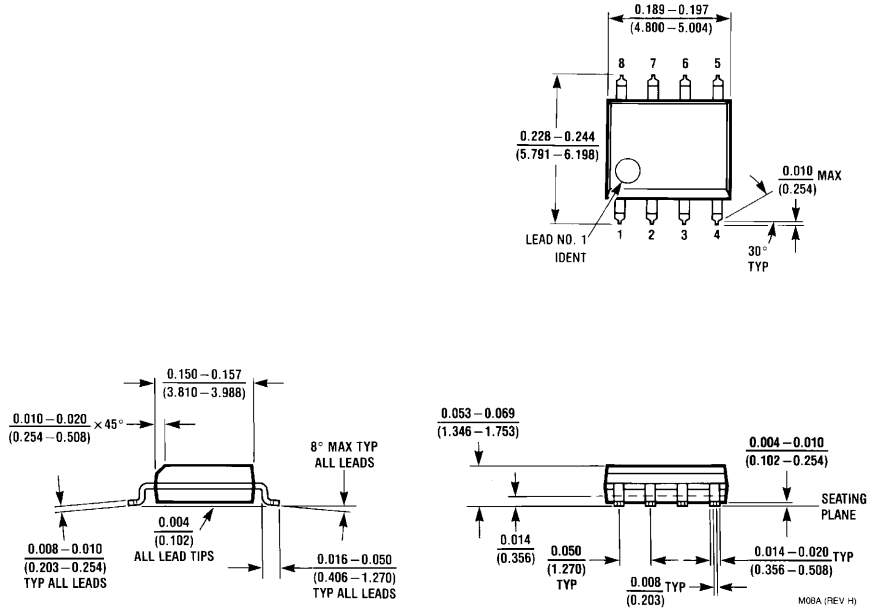
Adequate power supply bypassing is necessary to protect associated circuitry. Minimum recommended is 0.1µF in parallel with 1µF electrolytic.

Lower comparator storage time can be as long as 10µs when pin 2 is driven fully to ground for triggering. This limits the monostable pulse width to 10µs minimum.

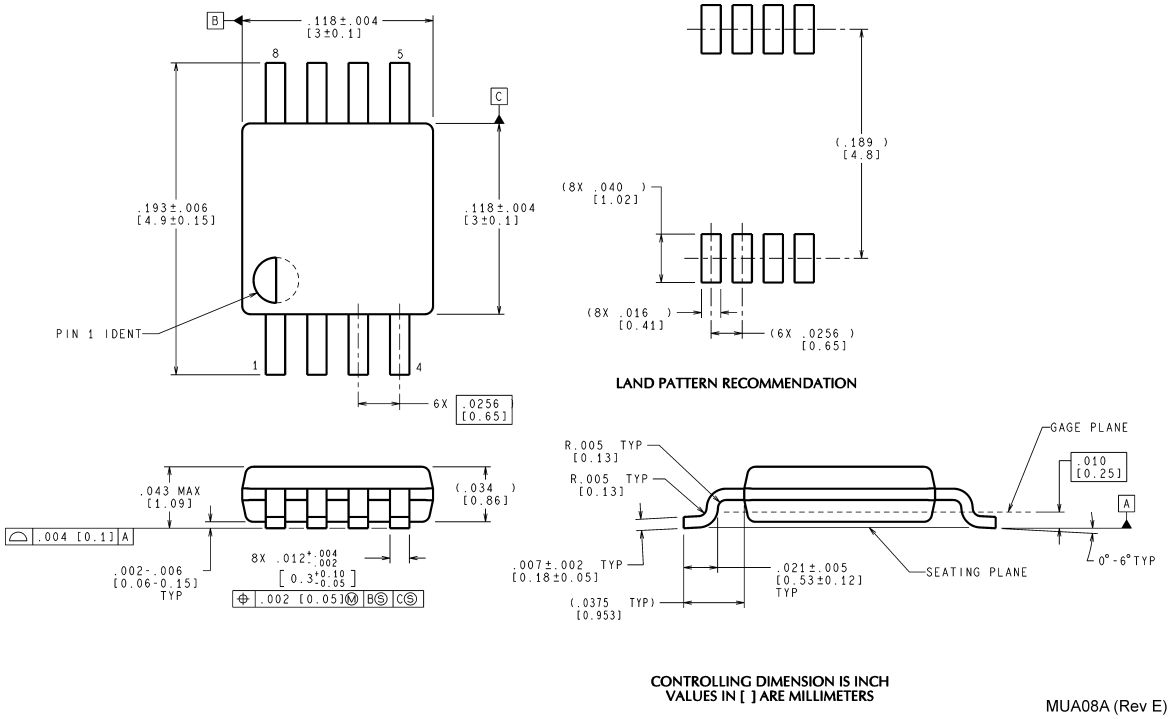
Delay time reset to output is 0.47µs typical. Minimum reset pulse width must be 0.3µs, typical.

Pin 7 current switches within 30ns of the output (pin 3) voltage.

Physical Dimensions inches (millimeters) unless otherwise noted

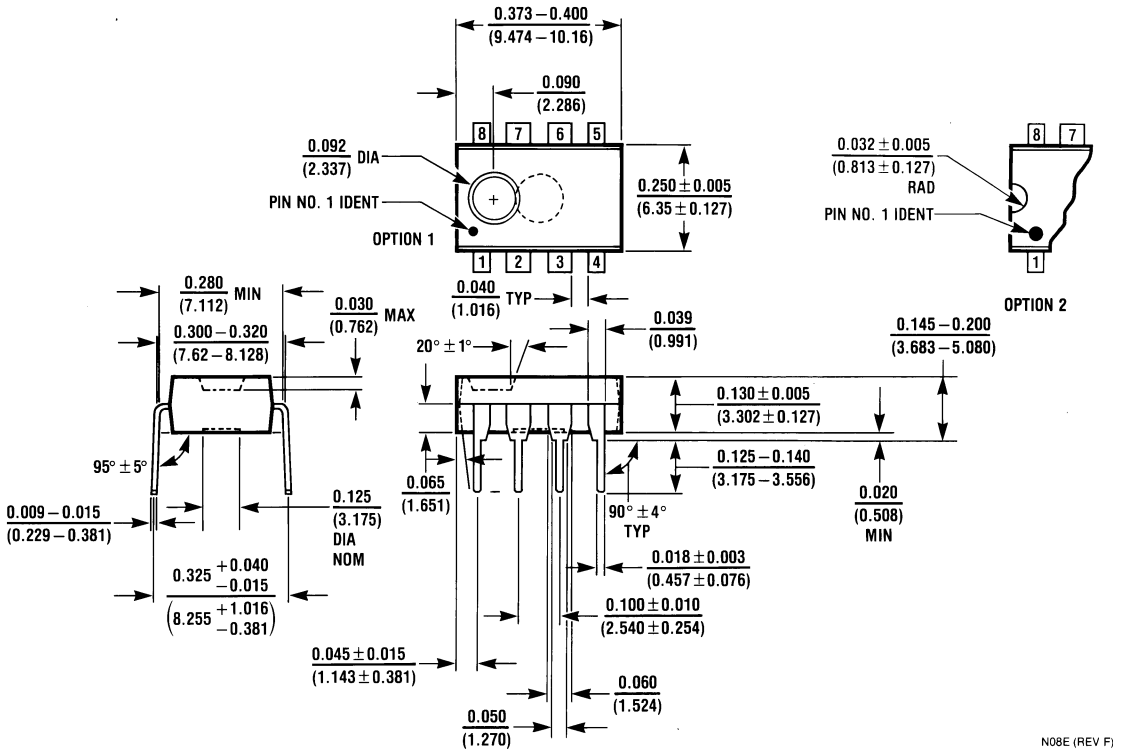


Small Outline Package (M)
NS Package Number M08A



8-Lead (0.118” Wide) Molded Mini Small Outline Package
NS Package Number MUA08A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



Molded Dual-In-Line Package (N)
NS Package Number N08E

National Semiconductor
Americas Customer
Support Center
Email: new.feedback@nsc.com
Tel: 1-800-272-9959

www.national.com

National Semiconductor
Europe Customer Support Center
Fax: +49 (0) 180-530 85 86
Email: europe.support@nsc.com
Deutsch Tel: +49 (0) 69 9508 6208
English Tel: +44 (0) 870 24 0 2171
Français Tel: +33 (0) 1 41 91 8790

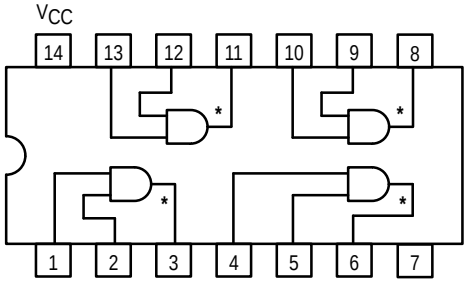
National Semiconductor
Asia Pacific Customer
Support Center
Email: ap.support@nsc.com

National Semiconductor
Japan Customer Support Center
Fax: 81-3-5639-7507
Email: jpn.feedback@nsc.com
Tel: 81-3-5639-7560

MOTOROLA

QUAD 2-INPUT AND GATE

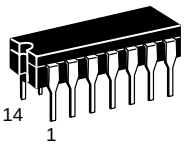
SN54/74LS09



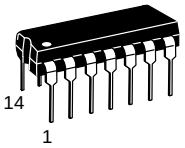
*OPEN COLLECTOR OUTPUTS

QUAD 2-INPUT AND GATE

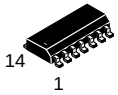
LOW POWER SCHOTTKY



J SUFFIX
CERAMIC
CASE 632-08



N SUFFIX
PLASTIC
CASE 646-06



D SUFFIX
SOIC
CASE 751A-02

ORDERING INFORMATION

SN54LSXXJ	Ceramic
SN74LSXXN	Plastic
SN74LSXXD	SOIC

GUARANTEED OPERATING RANGES

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	54 74	4.5 4.75	5.0 5.0	5.5 5.25	V
T_A	Operating Ambient Temperature Range	54 74	– 55 0	25 25	125 70	°C
V_{OH}	Output Voltage — High	54, 74			5.5	V
I_{OL}	Output Current — Low	54 74			4.0 8.0	mA

DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

Symbol	Parameter		Limits Min	Limits Typ	Limits Max	Unit	Test Conditions	
V_{IH}	Input HIGH Voltage		2.0			V	Guaranteed Input HIGH Voltage for All Inputs	
V_{IL}	Input LOW Voltage	54			0.7	V	Guaranteed Input LOW Voltage for All Inputs	
		74			0.8			
V_{IK}	Input Clamp Diode Voltage			−0.65	−1.5	V	V_{CC} = MIN, I_{IN} = −18 mA	
I_{OH}	Output HIGH Current	54, 74			100	μA	V_{CC} = MIN, V_{OH} = MAX	
V_{OL}	Output LOW Voltage	54, 74		0.25	0.4	V	I_{OL} = 4.0 mA	V_{CC} = V_{CC} MIN, V_{IN} = V_{IL} or V_{IH} per Truth Table
		74		0.35	0.5	V	I_{OL} = 8.0 mA	
I_{IH}	Input HIGH Current				20	μA	V_{CC} = MAX, V_{IN} = 2.7 V	
					0.1	mA	V_{CC} = MAX, V_{IN} = 7.0 V	
I_{IL}	Input LOW Current				−0.4	mA	V_{CC} = MAX, V_{IN} = 0.4 V	
I_{CC}	Power Supply Current Total, Output HIGH				4.8	mA	V_{CC} = MAX	
	Total, Output LOW				8.8			

AC CHARACTERISTICS (T_A = 25°C)

Symbol	Parameter	Limits Min	Limits Typ	Limits Max	Unit	Test Conditions
t_{PLH}	Turn-Off Delay, Input to Output		20	35	ns	V_{CC} = 5.0 V C_L = 15 pF, R_L = 2.0 kΩ
t_{PHL}	Turn-On Delay, Input to Output		17	35	ns	

FAIRCHILD SEMICONDUCTOR™

April 1988
Revised July 1999

74F11
Triple 3-Input AND Gate

General Description

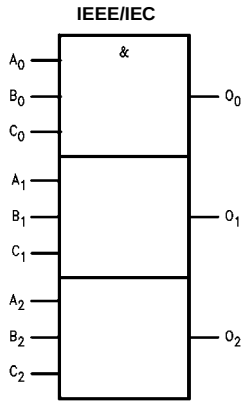
This device contains three independent gates, each of which performs the logic AND function.

Ordering Code:

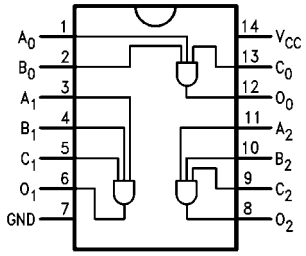
Order Number	Package Number	Package Description
74F11SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150 Narrow
74F11SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F11PC	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol



Connection Diagram



Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
A_n, B_n, C_n	Inputs	1.0/1.0	20 µA/–0.6 mA
O_n	Outputs	50/33.3	–1 mA/20 mA

Absolute Maximum Ratings(Note 1)

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−55°C to +125°C
Junction Temperature under Bias	−55°C to +150°C
V_{CC} Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA
Voltage Applied to Output	
in HIGH State (with V_{CC} = 0V)	
Standard Output	−0.5V to V_{CC}
3-STATE Output	−0.5V to +5.5V
Current Applied to Output	
in LOW State (Max)	twice the rated I_{OL} (mA)

Recommended Operating Conditions

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

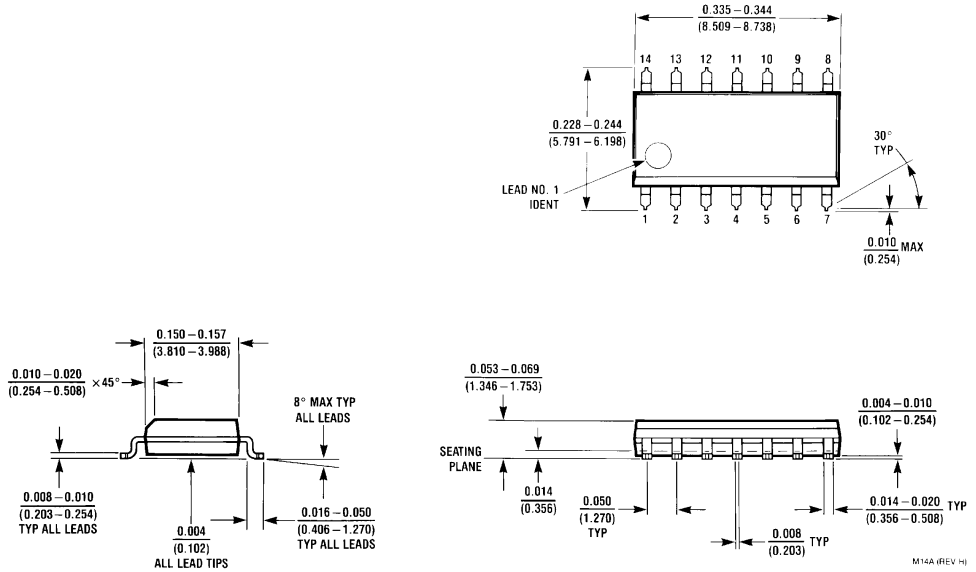
DC Electrical Characteristics

Symbol	Parameter		Min	Typ	Max	Units	V_{CC}	Conditions
V_{IH}	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal
V_{IL}	Input LOW Voltage				0.8	V		Recognized as a LOW Signal
V_{CD}	Input Clamp Diode Voltage				−1.2	V	Min	I_{IN} = −18 mA
V_{OH}	Output HIGH Voltage	10% V_{CC}	2.5			V	Min	I_{OH} = −1 mA
		5% V_{CC}	2.7					I_{OH} = −1 mA
V_{OL}	Output LOW Voltage	10% V_{CC}			0.5	V	Min	I_{OL} = 20 mA
I_{IH}	Input HIGH Current				5.0	µA	Max	V_{IN} = 2.7V
I_{BVI}	Input HIGH Current Breakdown Test				7.0	µA	Max	V_{IN} = 7.0V
I_{CEX}	Output HIGH Leakage Current				50	µA	Max	V_{OUT} = V_{CC}
V_{ID}	Input Leakage Test		4.75			V	0.0	I_{ID} = 1.9 µA All other pins grounded
I_{OD}	Output Leakage Circuit Current				3.75	µA	0.0	V_{IOD} = 150 mV All other pins grounded
I_{IL}	Input LOW Current				−0.6	mA	Max	V_{IN} = 0.5V
I_{OS}	Output Short-Circuit Current		−60		−150	mA	Max	V_{OUT} = 0V
I_{CCH}	Power Supply Current			4.1	6.2	mA	Max	V_O = HIGH
I_{CCL}	Power Supply Current			6.5	9.7	mA	Max	V_O = LOW

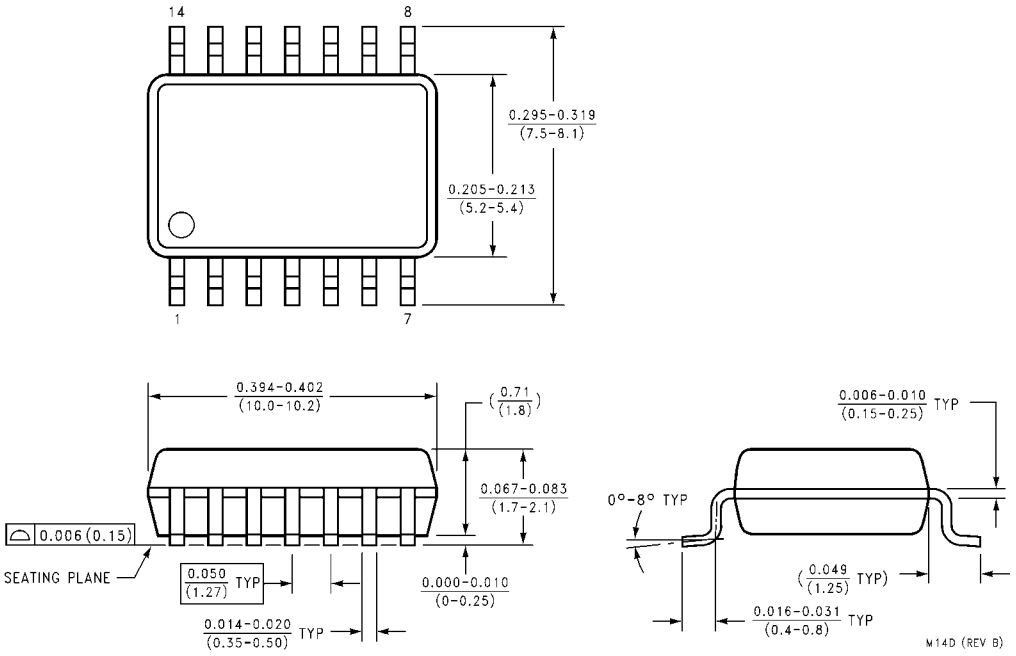
AC Electrical Characteristics

Symbol	Parameter	T_A = +25°C, V_{CC} = +5.0V, C_L = 50 pF			T_A −55°C to +125°C, V_{CC} = +5.0V, C_L = 50 pF		T_A = 0°C to +70°C, V_{CC} = +5.0V, C_L = 50 pF		Units
		Min	Typ	Max	Min	Max	Min	Max	
t_{PLH}	Propagation Delay	3.0	4.2	5.6	2.5	7.5	3.0	6.6	ns
t_{PHL}	A_n, B_n, C_n to O_n	2.5	4.1	5.5	2.0	7.5	2.5	6.5	

Physical Dimensions inches (millimeters) unless otherwise noted

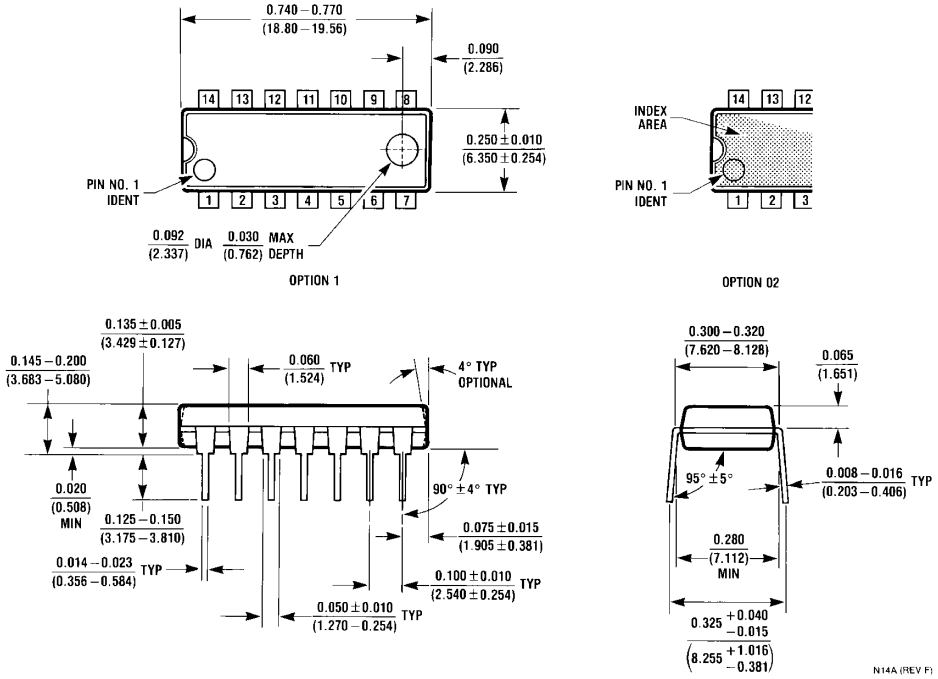


14-Lead Small Outline Integrated Circuit (SOC), JEDEC MS-120, 0.150 Narrow
Package Number M14A



14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M14D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

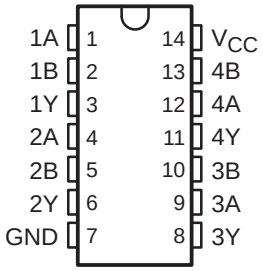


14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide
Package Number N14A

- **Qualification in Accordance With AEC-Q100†**
- **Qualified for Automotive Applications**
- **Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval**
- **Wide Operating Voltage Range of 2 V to 6 V**
- **Outputs Can Drive Up To 10 LSTTL Loads**
- **Low Power Consumption, 20-μA Max I_{CC}**
- **±4-mA Output Drive at 5 V**
- **Low Input Current of 1 μA Max**
- **True Logic**

† Contact factory for details. Q100 qualification data available on request.

D OR PW PACKAGE
(TOP VIEW)



description/ordering information

This device contains four independent 2-input exclusive-OR gates. They perform the Boolean function $Y = A \oplus B$ or $Y = \overline{A}B + A\overline{B}$ in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

ORDERING INFORMATION

T_A	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	SOIC − D	Reel of 2500	SN74HC86IDRQ1	HC86I
	TSSOP − PW	Reel of 2000	SN74HC86IPWRQ1	HC86I
−40°C to 125°C	SOIC − D	Reel of 2500	SN74HC86QDRQ1	HC86Q
	TSSOP − PW	Reel of 2000	SN74HC86QPWRQ1	HC86Q

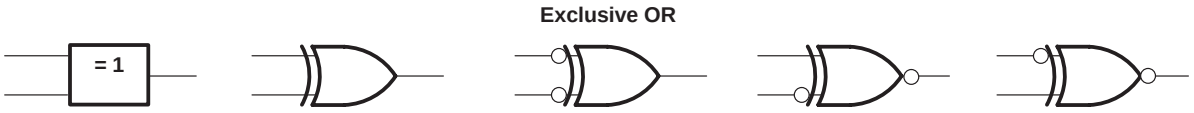
‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L

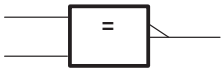
exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



These are five equivalent exclusive-OR symbols valid for an ’HC86 gate in positive logic; negation may be shown at any two ports.

Logic Identity Element

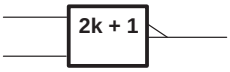


The output is active (low) if all inputs stand at the same logic level (i.e., A = B).

Even-Parity Element

The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

Odd-Parity Element



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1) . . . . . ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1) . . . . . ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) . . . . . ±25 mA
Continuous current through V_{CC} or GND . . . . . ±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package . . . . . 86°C/W
PW package . . . . . 113°C/W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		2	5	6	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5			V
		V_{CC} = 4.5 V	3.15			
		V_{CC} = 6 V	4.2			
V_{IL}	Low-level input voltage	V_{CC} = 2 V			0.5	V
		V_{CC} = 4.5 V			1.35	
		V_{CC} = 6 V			1.8	
V_I	Input voltage		0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	V
$\Delta t/\Delta v$	Input transition rise/fall time	V_{CC} = 2 V			1000	ns
		V_{CC} = 4.5 V			500	
		V_{CC} = 6 V			400	
T_A	Operating free-air temperature		−40		125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	T_A = −40°C TO 125°C		T_A = −40°C TO 85°C		UNIT
				MIN	MAX	MIN	MAX	
V_{OH}	$V_I = V_{IH}$ or V_{IL}	I_{OH} = −20 µA	2 V	1.9		1.9		V
			4.5 V	4.4		4.4		
			6 V	5.9		5.9		
		I_{OH} = −4 mA	4.5 V	3.7		3.84		
		I_{OH} = −5.2 mA	6 V	5.2		5.34		
V_{OL}	$V_I = V_{IH}$ or V_{IL}	I_{OL} = 20 µA	2 V		0.1		0.1	V
			4.5 V		0.1		0.1	
			6 V		0.1		0.1	
		I_{OL} = 4 mA	4.5 V		0.4		0.33	
		I_{OL} = 5.2 mA	6 V		0.4		0.33	
I_I	$V_I = V_{CC}$ or 0		6 V		±1000		±1000	nA
I_{CC}	$V_I = V_{CC}$ or 0,	I_O = 0	6 V		40		20	µA
C_i			2 V to 6 V		10		10	pF

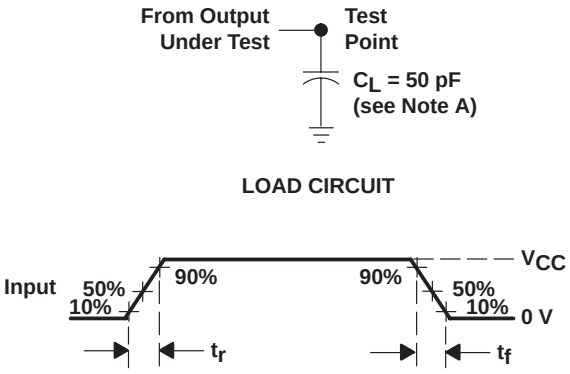
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = −40°C TO 125°C		T_A = −40°C TO 85°C		UNIT
				MIN	MAX	MIN	MAX	
t_{pd}	A or B	Y	2 V		150		125	ns
			4.5 V		30		25	
			6 V		25		21	
t_t		Y	2 V		110		95	ns
			4.5 V		22		19	
			6 V		19		16	

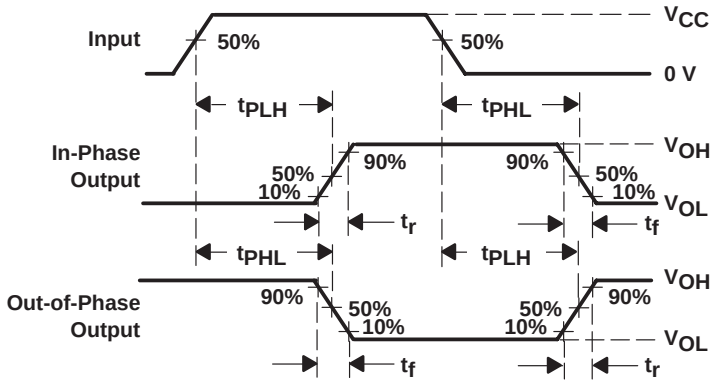
operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per gate	No load	35	pF

PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORM
INPUT RISE AND FALL TIMES

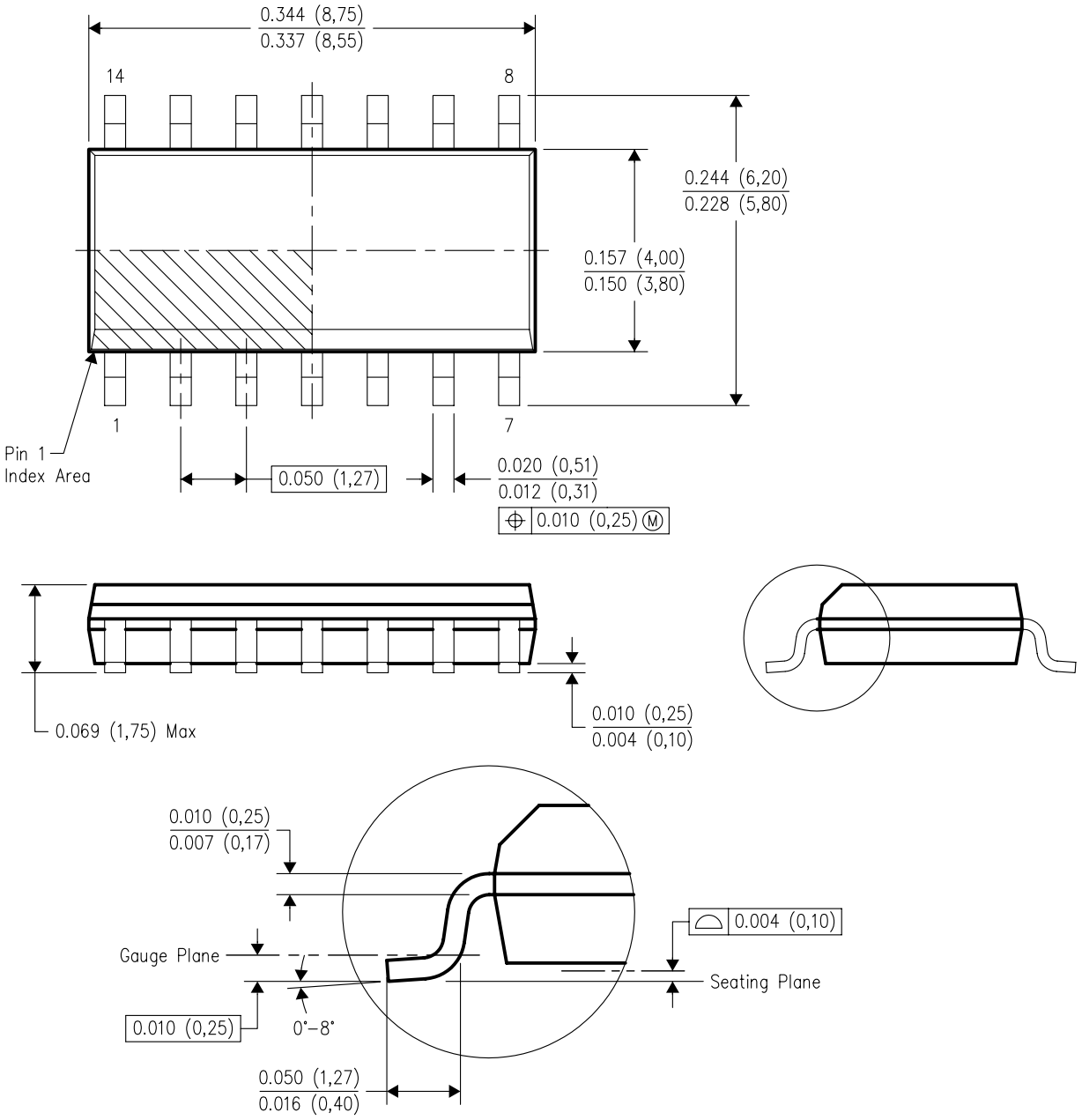


VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

NOTES: A. C_L includes probe and test-fixture capacitance.
B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 6 ns, t_f = 6 ns.
C. The outputs are measured one at a time, with one input transition per measurement.
D. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 1. Load Circuit and Voltage Waveforms

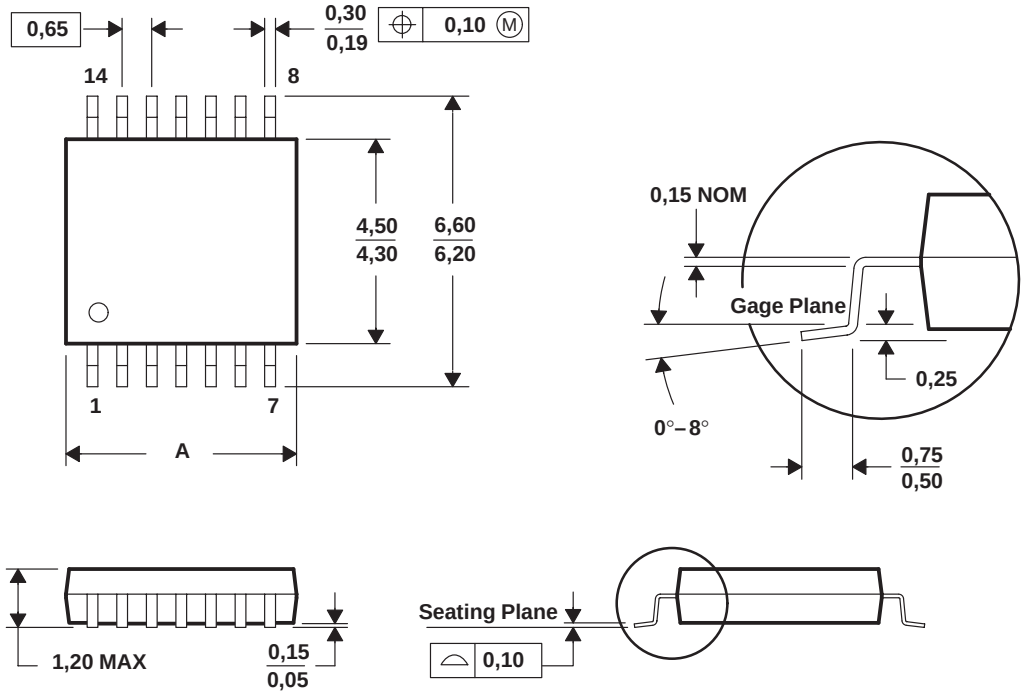
D (R–PDSO–G14) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–012 variation AB.

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

SDLS119 – DECEMBER 1983 – REVISED MARCH 1988

- **Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs**
- **Dependable Texas Instruments Quality and Reliability**

description

These devices contain two independent D-type positive-edge-triggered flip-flops. A low level at the preset or clear inputs sets or resets the outputs regardless of the levels of the other inputs. When preset and clear are inactive (high), data at the D input meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the D input may be changed without affecting the levels at the outputs.

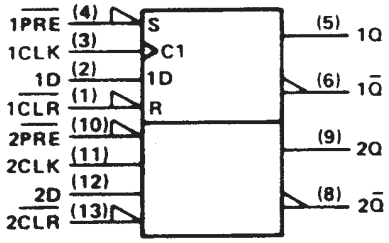
The SN54' family is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74' family is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS				OUTPUTS	
$\overline{PRE}$	$\overline{CLR}$	CLK	D	Q	$\overline{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H†	H†
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q_0	$\overline{Q}_0$

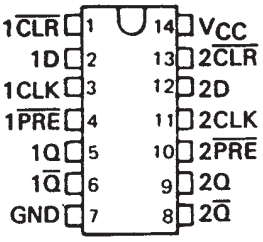
† The output levels in this configuration are not guaranteed to meet the minimum levels in V_{OH} if the lows at preset and clear are near V_{IL} maximum. Furthermore, this configuration is nonstable; that is, it will not persist when either preset or clear returns to its inactive (high) level.

logic symbol‡

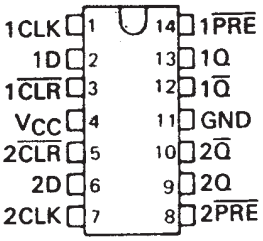


‡This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

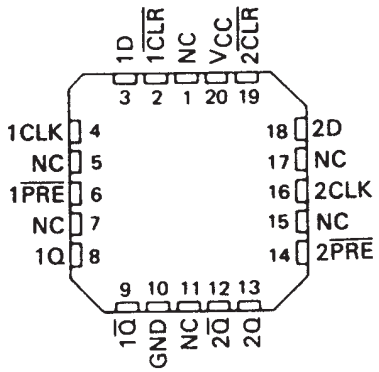
SN5474 . . . J PACKAGE
SN54LS74A, SN54S74 . . . J OR W PACKAGE
SN7474 . . . N PACKAGE
SN74LS74A, SN74S74 . . . D OR N PACKAGE
(TOP VIEW)



SN5474 . . . W PACKAGE
(TOP VIEW)

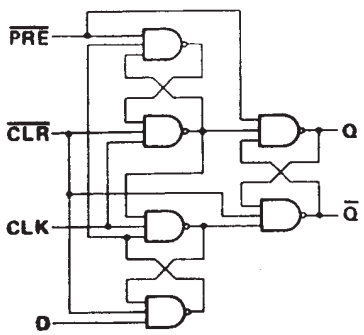


SN54LS74A, SN54S74 . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

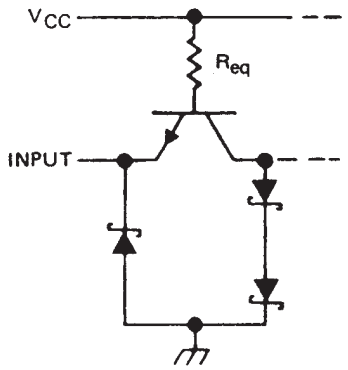
logic diagram (positive logic)



schematics of inputs and outputs

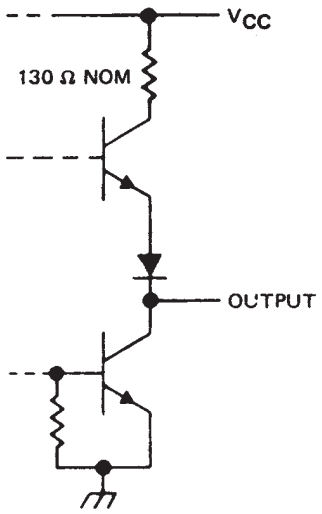
'74

EQUIVALENT OF EACH INPUT



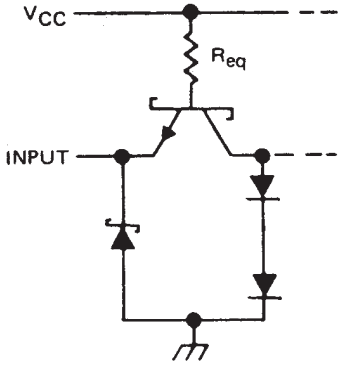
I_{IL} MAX	R_{eq} NOM
–1.6 mA	4 kΩ
–3.2 mA	2 kΩ

TYPICAL OF ALL OUTPUTS



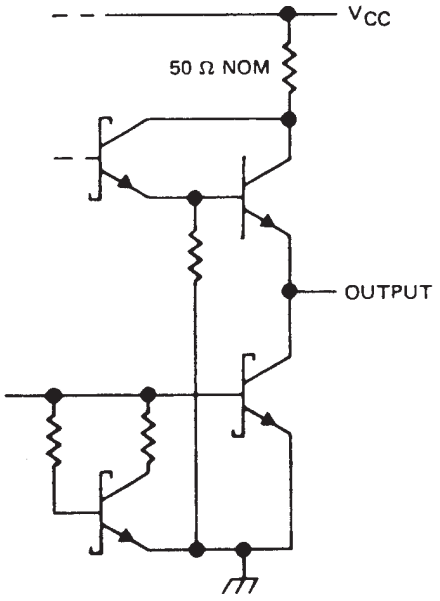
'S74

EQUIVALENT OF EACH INPUT



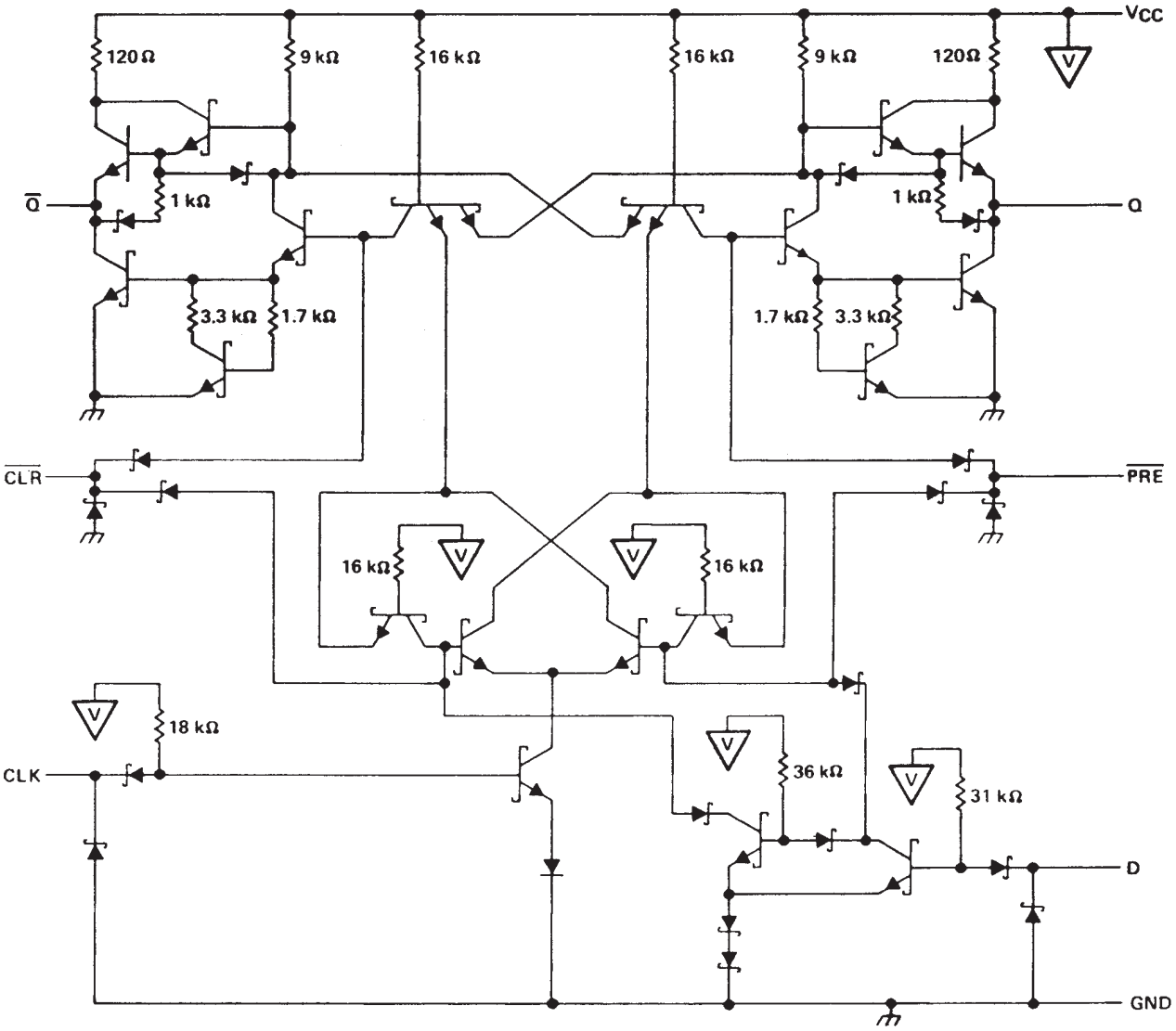
I_{IL} MAX	R_{eq} NOM
–2 mA	2.8 kΩ
–4 mA	1.4 kΩ
–6 mA	940 Ω

TYPICAL OF ALL OUTPUTS



schematic

'LS74A



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage: '74, 'S74 . . . . . 5.5 V
'LS74A . . . . . 7 V
Operating free-air temperature range: SN54' . . . . . −55°C to 125°C
SN74' . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

			SN5474			SN7474			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.8			0.8	V
I_{OH}	High-level output current				−0.4			−0.4	mA
I_{OL}	Low-level output current				16			16	mA
t_w	Pulse duration	CLK high	30			30			ns
		CLK low	37			37			
		$\overline{PRE}$ or $\overline{CLR}$ low	30			30			
t_{su}	Input setup time before CLK↑		20			20			ns
t_h	Input hold time-data after CLK↑		5			5			ns
T_A	Operating free-air temperature		−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	SN5474			SN7474			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}		V_{CC} = MIN, I_I = −12 mA			−1.5			−1.5	V
V_{OH}		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OH} = −0.4 mA	2.4	3.4		2.4	3.4		V
V_{OL}		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OL} = 16 mA		0.2	0.4		0.2	0.4	V
I_I		V_{CC} = MAX, V_I = 5.5 V			1			1	mA
I_{IH}	D	V_{CC} = MAX, V_I = 2.4 V			40			40	μA
	$\overline{CLR}$				120			120	
	All Other				80			80	
I_{IL}	D	V_{CC} = MAX, V_I = 0.4 V			−1.6			−1.6	mA
	$\overline{PRE}$§				−1.6			−1.6	
	$\overline{CLR}$§				−3.2			−3.2	
	CLK				−3.2			−3.2	
I_{OS}¶		V_{CC} = MAX	−20		−57	−18		−57	mA
I_{CC}#		V_{CC} = MAX, See Note 2		8.5	15		8.5	15	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Clear is tested with preset high and preset is tested with clear high.
¶Not more than one output should be shown at a time.
#Average per flip-flop.
NOTE 2: With all outputs open, I_{CC} is measured with the Q and $\overline{Q}$ outputs high in turn. At the time of measurement, the clock input is grounded.

switching charateristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}			R_L = 400 Ω, C_L = 15 pF	15	25		MHz
t_{PLH}	$\overline{PRE}$ or $\overline{CLR}$	Q or $\overline{Q}$				25	ns
t_{PHL}						40	ns
t_{PLH}	CLK	Q or $\overline{Q}$			14	25	ns
t_{PHL}					20	40	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

			SN54LS74A			SN74LS74A			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.7			0.8	V
I_{OH}	High-level output current				−0.4			−0.4	mA
I_{OL}	Low-level output current				4			8	mA
f_{clock}	Clock frequency		0		25	0		25	MHz
t_w	Pulse duration	CLK high	25			25			ns
		$\overline{PRE}$ or $\overline{CLR}$ low	25			25			
t_{su}	Setup time-before CLK↑	High-level data	20			20			ns
		Low-level data	20			20			
t_h	Hold time-data after CLK↑		5			5			ns
T_A	Operating free-air temperature		−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†			SN54LS74A			SN74LS74A			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}		V_{CC} = MIN,	I_I = −18 mA				−1.5			−1.5	V
V_{OH}		V_{CC} = MIN, I_{OH} = −0.4 mA	V_{IH} = 2 V,	V_{IL} = MAX,	2.5	3.4		2.7	3.4		V
V_{OL}		V_{CC} = MIN, I_{OL} = 4 mA	V_{IL} = MAX,	V_{IH} = 2 V,		0.25	0.4		0.25	0.4	V
		V_{CC} = MIN, I_{OL} = 8 mA	V_{IL} = MAX,	V_{IH} = 2 V,					0.35	0.5	
I_I	D or CLK	V_{CC} = MAX,	V_I = 7 V				0.1			0.1	mA
	$\overline{CLR}$ or $\overline{PRE}$						0.2			0.2	
I_{IH}	D or CLK	V_{CC} = MAX,	V_I = 2.7 V				20			20	μA
	$\overline{CLR}$ or $\overline{PRE}$						40			40	
I_{IL}	D or CLK	V_{CC} = MAX,	V_I = 0.4 V				−0.4			−0.4	mA
	$\overline{CLR}$ or $\overline{PRE}$						−0.8			−0.8	
I_{OS}§		V_{CC} = MAX,	See Note 4		−20		−100	−20		−100	mA
I_{CC} (Total)		V_{CC} = MAX,	See Note 2			4	8		4	8	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.
NOTE 2: With all outputs open, I_{CC} is measured with the Q and $\overline{Q}$ outputs high in turn. At the time of measurement, the clock input is grounded.
NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V_O = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
f_{max}			R_L = 2 kΩ,	C_L = 15 pF	25	33		MHz
t_{PLH}	$\overline{CLR}$, $\overline{PRE}$ or CLK	Q or $\overline{Q}$				13	25	ns
t_{PHL}						25	40	ns

Note 3: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

			SN54S74			SN74S74			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.8			0.8	V
I_{OH}	High-level output current				−1			−1	mA
I_{OL}	Low-level output current				20			20	mA
t_w	Pulse duration	CLK high	6			6			ns
		CLK low	7.3			7.3			
		$\overline{CLR}$ or $\overline{PRE}$ low	7			7			
t_{su}	Setup time, before CLK ↑	High-level data	3			3			ns
		Low-level data	3			3			
t_h	Input hold time - data after CLK ↑		2			2			ns
T_A	Operating free-air temperature		−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	SN54S74			SN74S74			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}		V_{CC} = MIN, I_I = −18 mA,			−1.2			−1.2	V
V_{OH}		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OH} = −1 mA	2.5	3.4		2.7	3.4		V
V_{OL}		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OL} = 20 mA			0.5			0.5	V
I_I		V_{CC} = MAX, V_I = 5.5 V			1			1	mA
I_{IH}	D	V_{CC} = MAX, V_I = 2.7 V			50			50	μA
	$\overline{CLR}$				150			150	
	$\overline{PRE}$ or CLK				100			100	
I_{IL}	D	V_{CC} = MAX, V_I = 0.5 V			−2			−2	mA
	$\overline{CLR}$¶				−6			−6	
	$\overline{PRE}$¶				−4			−4	
	CLK				−4			−4	
I_{OS}§		V_{CC} = MAX	−40		−100	−40		−100	mA
I_{CC}#		V_{CC} = MAX, See Note 2		15	25		15	25	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.
¶Clear is tested with preset high and preset is tested with clear high.
#Average per flip-flop.
NOTE 2: With all outputs open, I_{CC} is measured with the Q and $\overline{Q}$ outputs high in turn. At the time of measurement, the clock input is grounded.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}			R_L = 280 Ω, C_L = 15 pF	75	110		MHz
t_{PLH}	$\overline{PRE}$ or $\overline{CLR}$	Q or $\overline{Q}$			4	6	ns
t_{PHL}	$\overline{PRE}$ or $\overline{CLR}$ (CLK high)	$\overline{Q}$ or Q			9	13.5	ns
	$\overline{PRE}$ or $\overline{CLR}$ (CLK low)				5	8	
t_{PLH}	CLK	Q or $\overline{Q}$			6	9	ns
t_{PHL}					6	9	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
JM38510/00205BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
JM38510/00205BDA	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
JM38510/00205BDA	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
JM38510/07101BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/07101BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/07101BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/07101BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30102B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30102B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30102BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30102BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30102BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30102BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30102SCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30102SCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30102SDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30102SDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN5474J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN5474J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54LS74AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS74AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54S74J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54S74J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN7474DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN7474DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN7474N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7474N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7474N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7474N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS74AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
						no Sb/Br)		
SN74LS74ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS74AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS74AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS74AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS74AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS74AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS74ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS74ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS74ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S74N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S74N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN74S74N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S74NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S74NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S74NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ5474J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5474J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5474W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ5474W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ54LS74AFK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS74AFK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS74AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS74AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS74AW	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS74AW	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S74FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S74FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S74J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S74J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S74W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S74W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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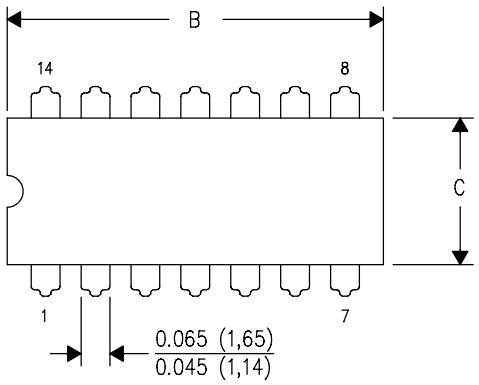
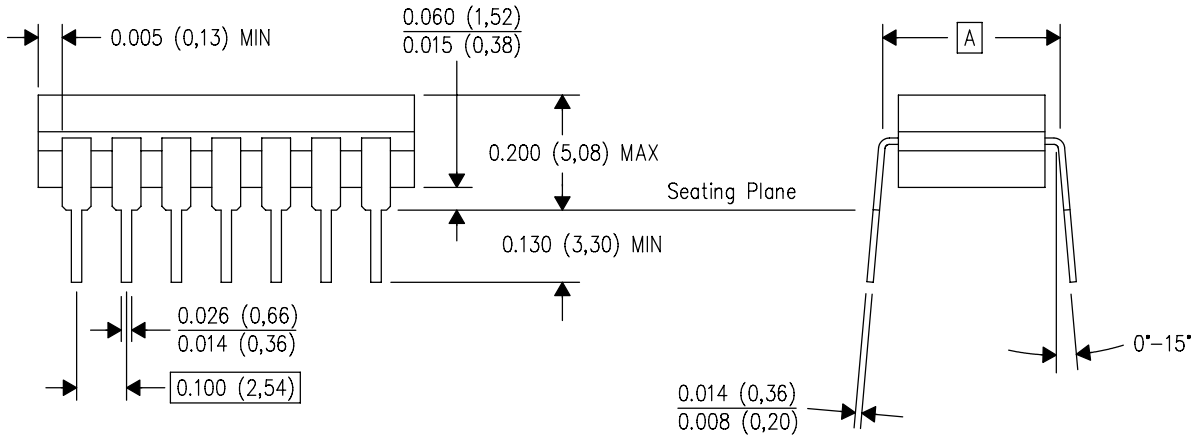
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



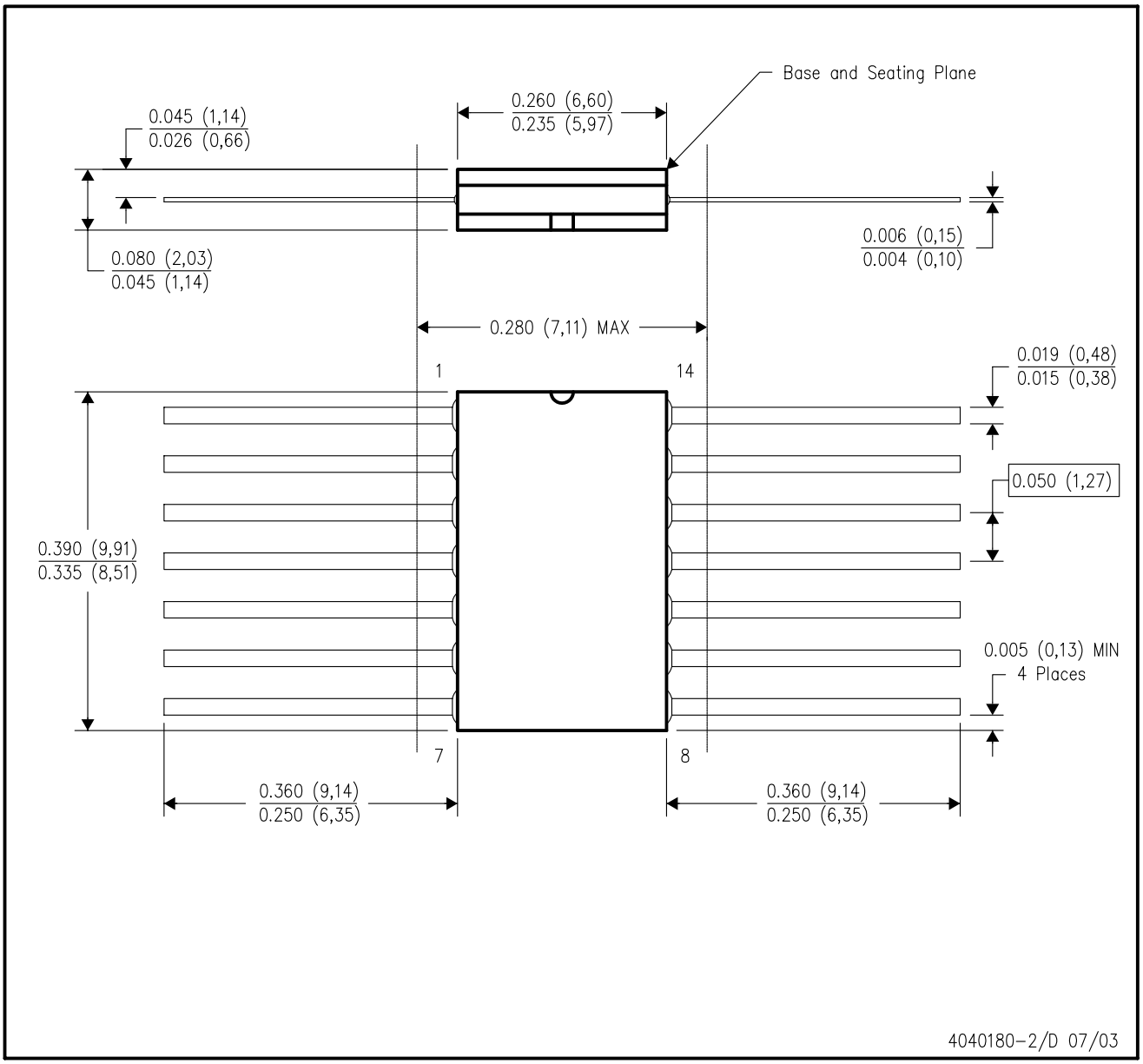
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

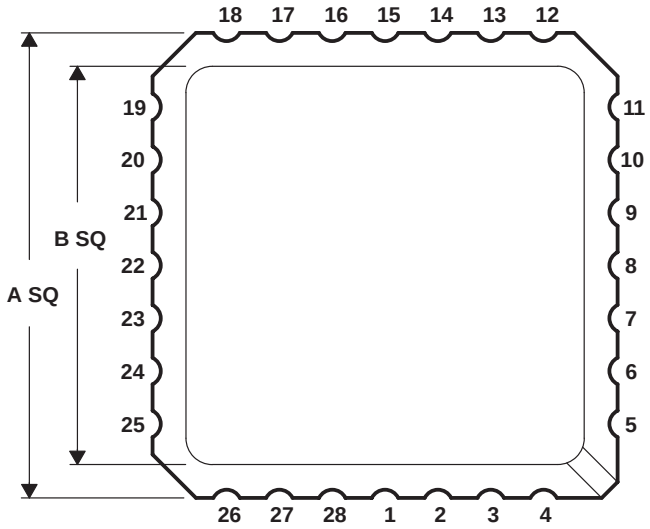
W (R–GDFP–F14) CERAMIC DUAL FLATPACK



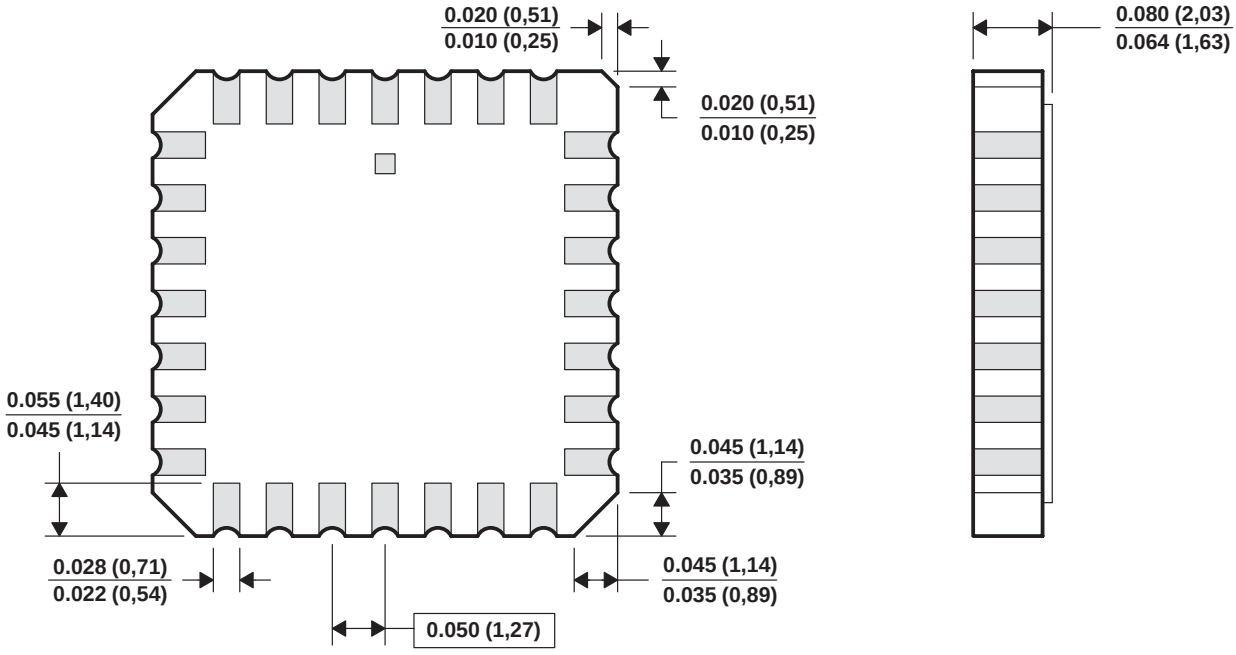
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14 and JEDEC MO–092AB

FK (S-CQCC-N)** **LEADLESS CERAMIC CHIP CARRIER**

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



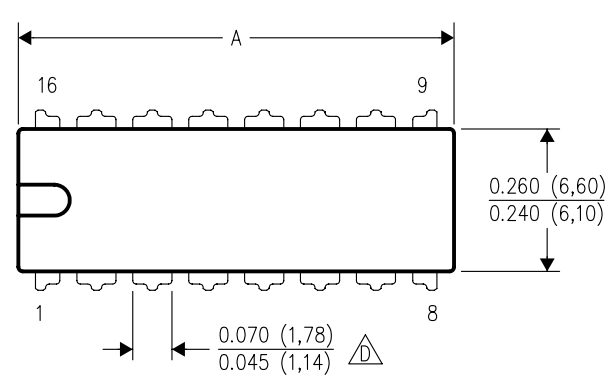
4040140/D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

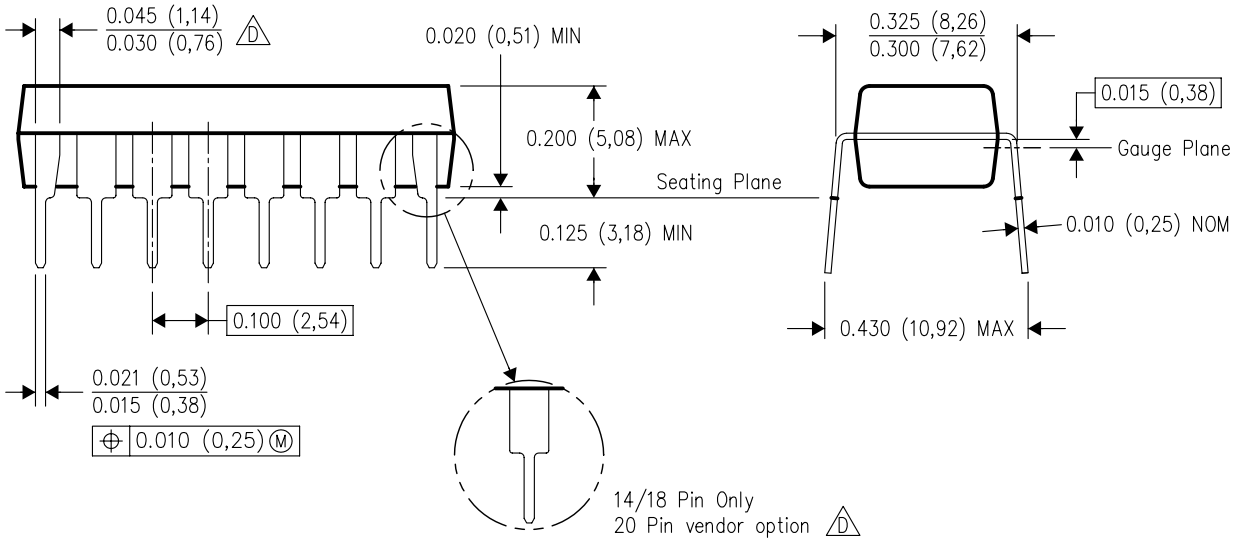
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



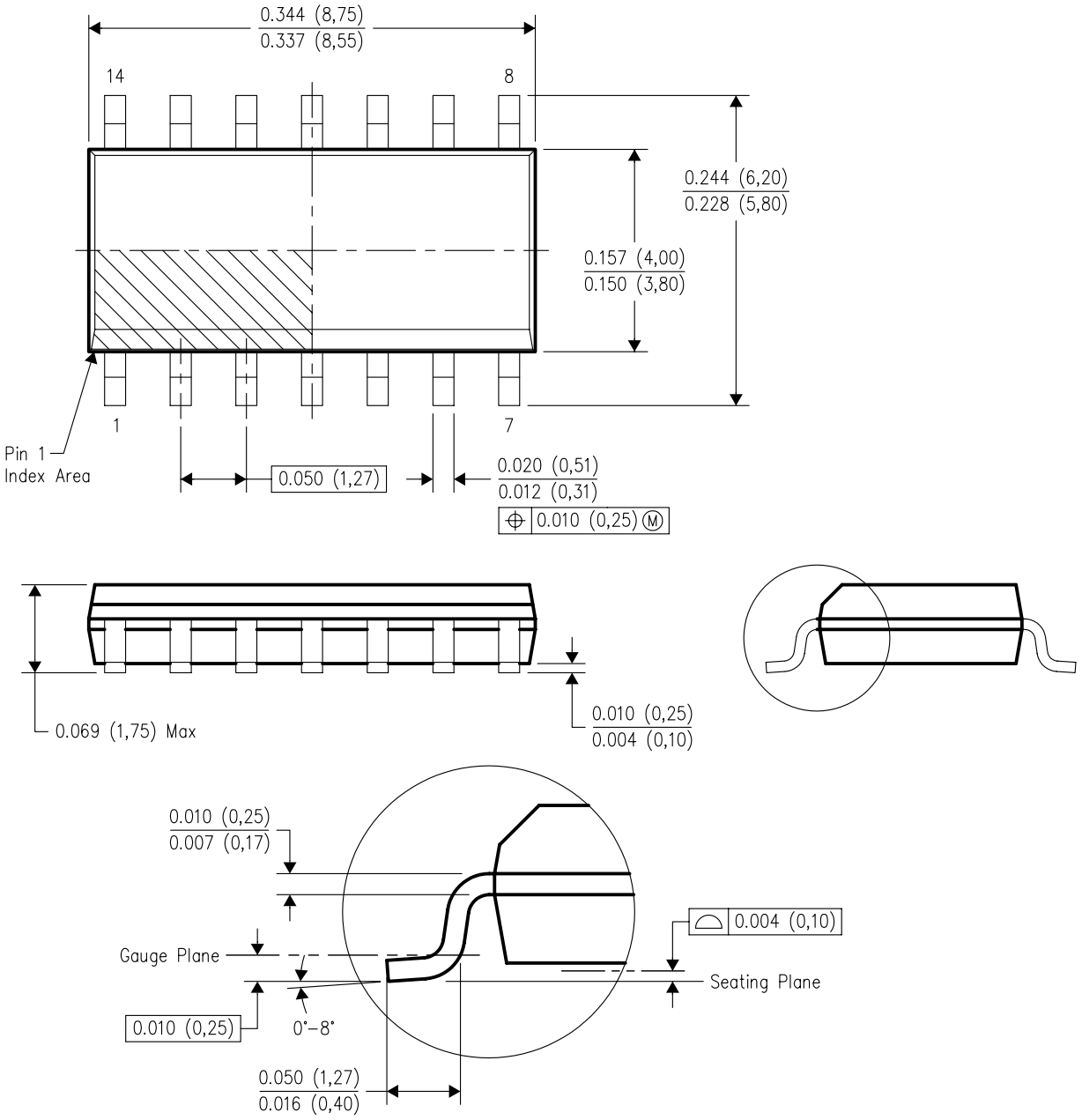
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G14) PLASTIC SMALL–OUTLINE PACKAGE

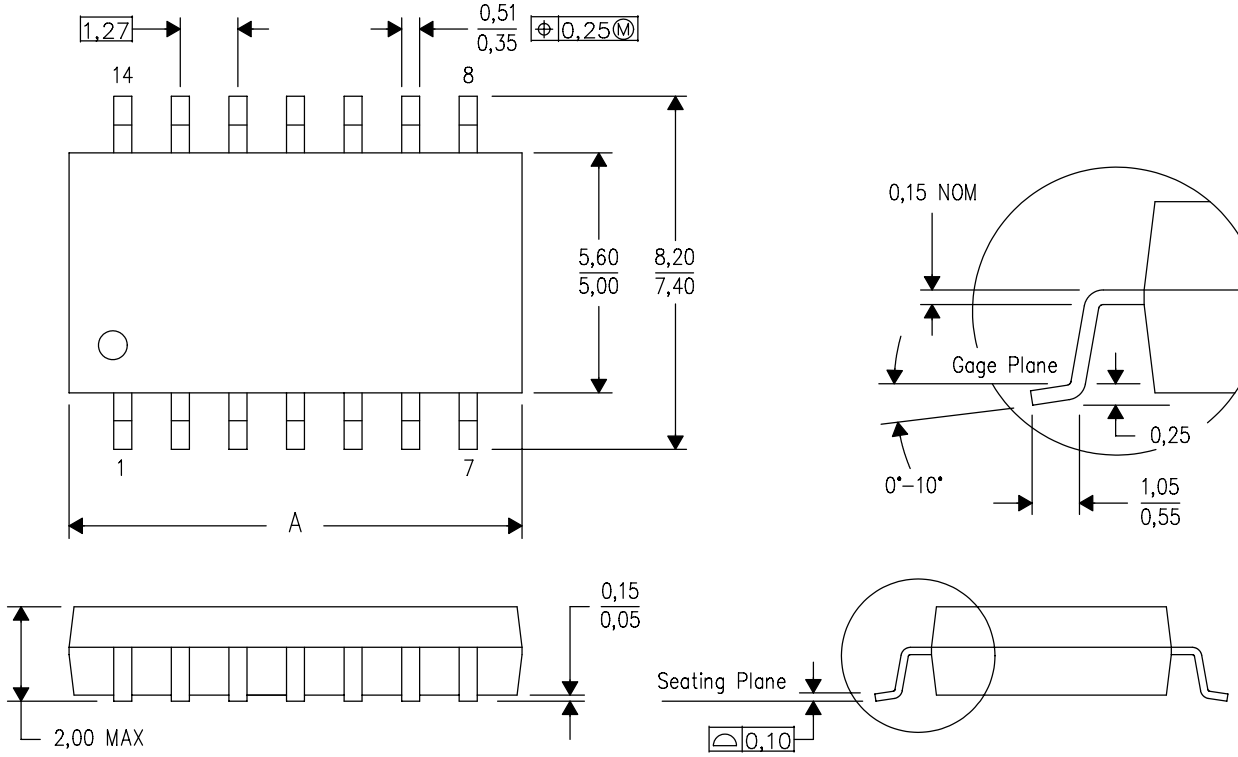


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–012 variation AB.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

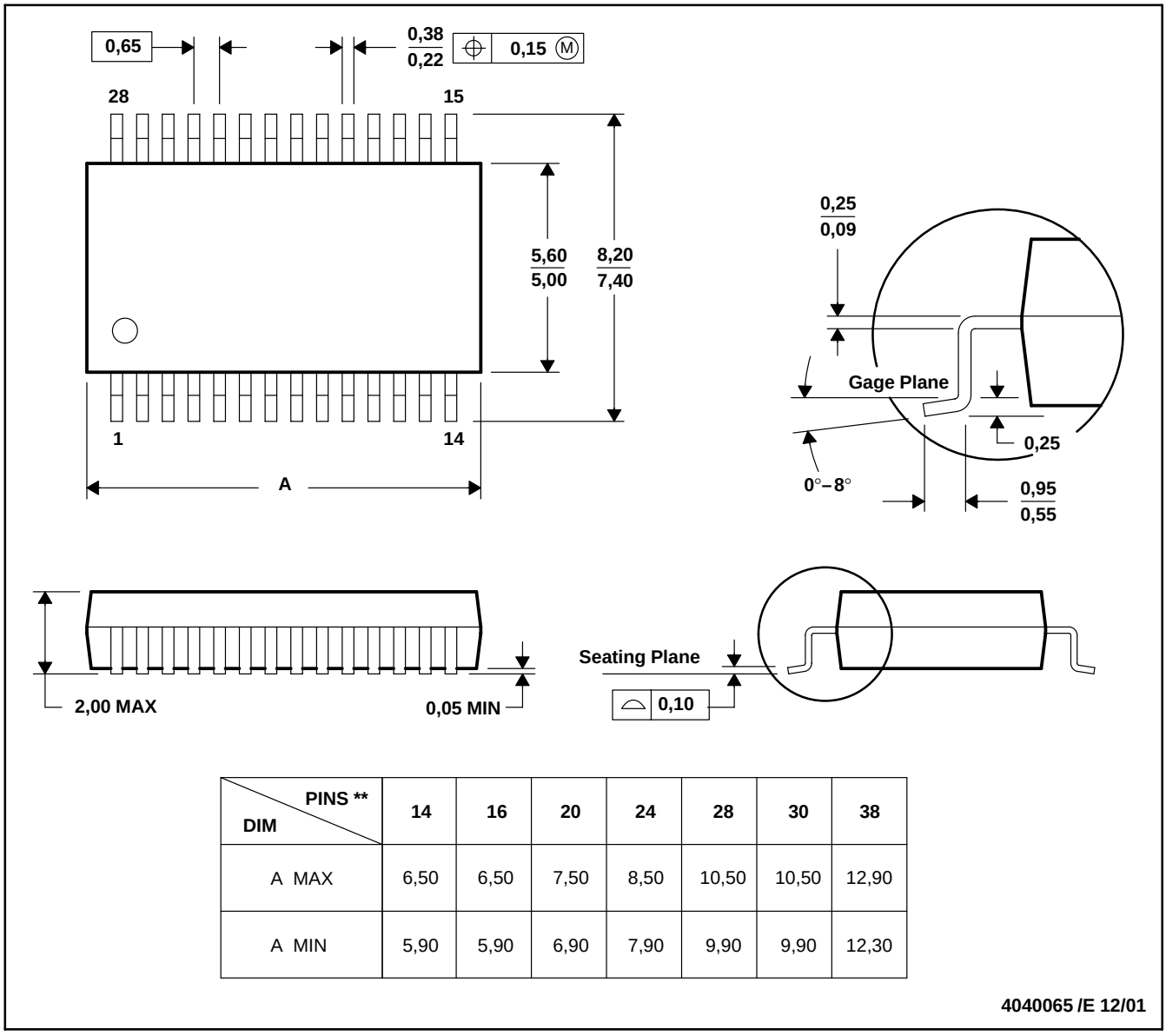
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

MSSO002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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State Decoder

```
module state_decoder (S0,S1,S2,S01,S02,S03,S04,S05,S06,S07,S08); //Declaration port input and output
input S0,S1,S2;          // State decoder input signals
output S01,S02,S03,S04,S05,S06,S07,S08;  // State decoder outputs

        assign S01 = ~S2 & ~S1 & ~S0;       // State output1
        assign S02 = ~S2 & ~S1 & S0;        // State output2
        assign S03 = ~S2 & S1 & ~S0;        // State output3
        assign S04 = ~S2 & S1 & S0;         // State output4
        assign S05 = S2 & ~S1 & ~S0;        // State output5
        assign S06 = S2 & ~S1 & S0;         // State output6
        assign S07 = S2 & S1 & ~S0;         // State output7
        assign S08 = S2 & S1 & S0;          // State output8

        endmodule     // End port declaration
```

Output Logic

```
module output_logic(S01,S02,S03,S04,S05,S06,S07,S08,G1,Y1,R1, GL1,G2,Y2,R2,GL2, G3,Y3,R3,GL3,G4,Y4,R4,GL4 ); // Declaration of  input and output output_logic module
input S01,S02,S03,S04,S05,S06,S07,S08; // Declaration input
output   G1,Y1,R1,GL1,G2,Y2,R2,GL2,G3,Y3,R3,GL3,G4,Y4,R4,GL4;   //  Declaration output of output_ logic

        assign GL1 = S01+ S02 + S03+ S04; // Road1 Green (left-sign)
        assign G1 = S01; // Road1 Green
        assign Y1 = S02; // Road1 Yellow
        assign R1 = S03 + S04 + S05 +S06 + S07 + S08; // Road1 Red
        assign GL2 = S03 + S04 + S05 + S06; // Road2 Green (left-sign)
        assign G2 = S03; Road2 Green
        assign Y2 = S04; // Road2 Yellow
```

```
        assign R2 = S01 + S02 + S05 +  S06 + S07 + S08; // Road2 Red
        assign GL3 = S05 + S06 + S07 + S08; // Road3 Green (left-sign)
        assign G3 = S05; // Road3 Green
        assign Y3 = S06; // Road3 Yellow
        assign R3 = S01 + S02 + S03 + S04 + S07 +  S08; // Road3 Red
        assign GL4 =S01 + S02 + S07 + S08; // Road4 Green (left-sign)
        assign G4 = S07;  // Road4 Green
        assign Y4 = S08; // Road4 Yellow
        assign R4 = S01 + S02 + S03 +  S04 + S05 + S06; // Road4 Red
endmodule
```

Trigger Logic

```
module trigger_logic (S01,S02,S03,S04,S05,S06,S07,S08,Short,Long); // Declaration input and output
input S01,S02,S03,S04,S05,S06,S07,S08; // Input declaration
output Short,Long; // Output declaration

        assign Long = (S01 + S03 + S05 + S07); // Long timer output
        assign Short = (S02 + S04 + S06 + S08); // Short timer output

endmodule
```

Combinational Logic (State decoder, output logic & trigger logic)

```
module combinational_logic ( S0,S1,S2,GL1,G1,Y1,R1,GL2,G2,Y2,R2, GL3, G3, Y3, R3, GL4, G4, Y4, R4, Long, Short); // Module delaration
input S0,S1,S2; // Input declaration from state decoder
output  GL1,G1,Y1,R1,GL2,G2,Y2,R2,GL3,G3,Y3,R3,GL4,G4,Y4,R4;  // Declaration output signals
output Long, Short; // Output timing
wire w1,w2,w3,w4,w5,w6,w7,w8; // to connect the module
```

```
    state_decoder N1 (S0,S1,S2,w1,w2,w3,w4,w5,w6,w7,w8); // State decoder module
    output_logic N2 (w1,w2,w3,w4,w5,w6,w7,w8,G1,Y1,R1,GL1,G2,Y2, R2, GL2,
    G3, Y3, R3, GL3, G4, Y4, R4, GL4); // Output logic module
    trigger_logic N3(w1,w2,w3,w4,w5,w6,w7,w8,Short,Long); // Trigger module for
    long and short timer
endmodule
```

D flip-flop

```
module D_flipflop (clock, D, Q); // Module declaration – input & output
input D;        // Input of D flip-flop
input clock;    // Clock input
output Q;       // Output of D flip-flop
reg Q;          // Register output

    always @ (negedge clock)     // high went see nededge clock
                Q <=D;
endmodule
```

Input Logic

```
module input_logic (TS,TL,Vs,Q0,Q1,Q2,D0,D1,D2);       //Module declaration
input TS,TL,Vs,Q0,Q1,Q2;   // input declaration
output D0,D1,D2;      // output declaration

    assign D0
        = ((Q0 & TS) | (~Q1 & ~Q0 & ~TL & Vs) | (Q1 & ~Q0 & ~TL) |  (Q1 &
        ~Q0 &  ~Vs)); // output1
    assign D1
        = ((Q0 & (Q1 ~^ TS)) | (Q1 & ~Q0 & TL & Vs) | (Q1 & ~Q0 & ~TL) | (Q1
        & ~Q0 & ~Vs)); // Output2
    assign D2
```

```
        = ((Q0 & ~TS) & (Q2 ^ Q1) | (Q2 & Q0 & TS) | (Q2 & ~Q0) &(Q1^ TL) |
        (Q2 & ~Q0 & ~Vs) | (Q2 & ~Q0 & Vs) & (Q1 ~^  TL)); // Output3
endmodule
```

Sequential Logic (D flip-flop & input logic)

```
module sequential_logic (clock,TS,TL,Vs,S0,S1,S2 ); // Module declaration
input clock;    // clock input
input TS,TL,Vs;        // declaration sequential logic inputs
output S0,S1,S2;       // declaration sequential logic outputs
wire w1,w2,w3;         // connection of module

    input_logic (TS, TL, Vs, S0, S1, S2, w1, w2, w3); // input logic module
    D_flipflop D1 (clock, w1, S0); // first bit counter module
    D_flipflop D2 (clock, w2, S1); // second bit counter module
    D_flipflop D3 (clock, w3, S2); third bit counter module

endmodule
```

Combination of Sequential & Combinational Logic

```
module sequence_combine (clock,TS,TL,Vs,GL1,G1,Y1,R1,GL2,G2,Y2,R2,GL3,G3,
Y3,R3,GL4,G4,Y4,R4,Long,Short);   // Module declaration
input clock;     // input clock
input TS, TL, Vs;       // input module declaration
output GL1,G1,Y1,R1,GL2,G2,Y2,R2,GL3,G3,Y3,R3,GL4,G4,Y4,R4,Long,Short;
// output module declaration
wire S0,S1,S2;   // jumper to connect a modules

    sequential_logic (clock,TS,TL,Vs,S0,S1,S2); // sequential logic module
    combinational_logic(S0,S1,S2,GL1,G1,Y1,R1,GL2,G2,Y2,R2,GL3,G3,Y3
    ,R3,GL4,G4,Y4,R4,Long,Short); // combinational logic module
endmodule
```